

## Topic 4

### ASIC Design Flow III

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**November 4<sup>th</sup>, 2024**



# Physical Synthesis Flow

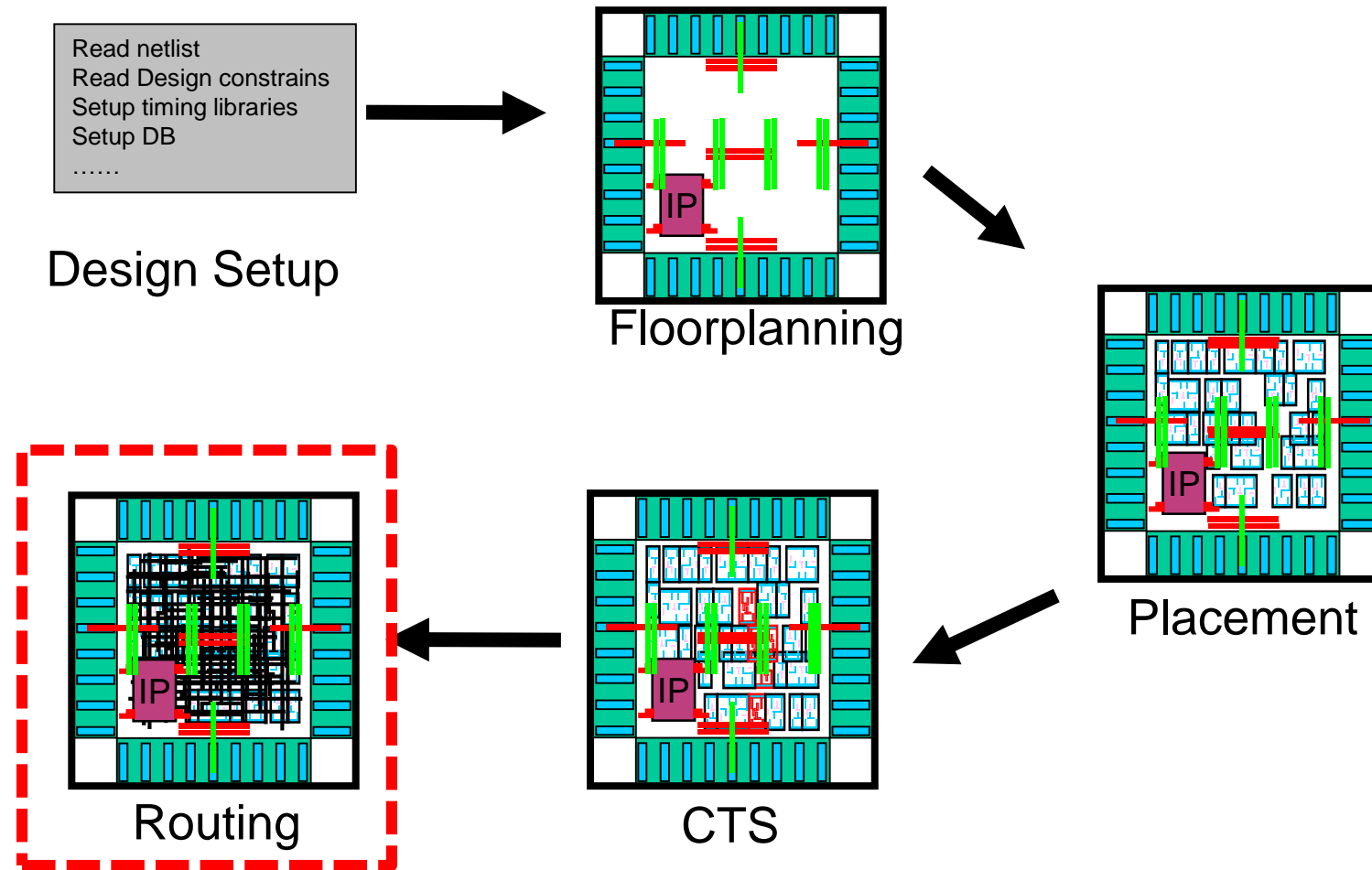
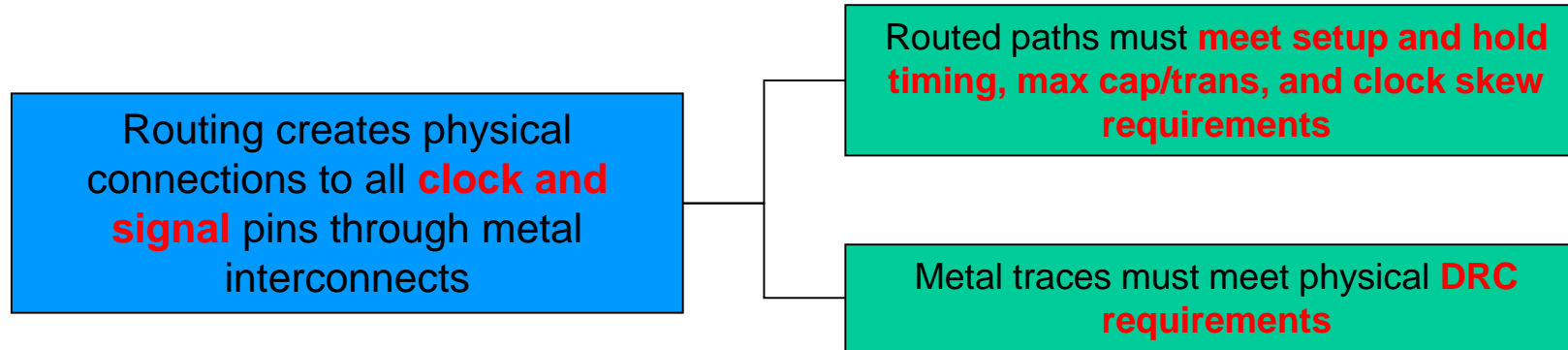


Figure: Synopsys

# Routing

Time to connect everything...

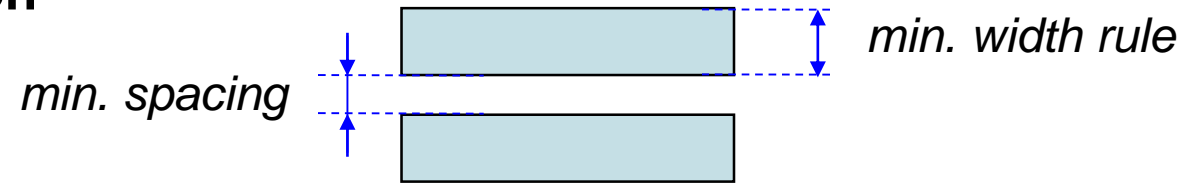
# Routing Fundamentals: Goal



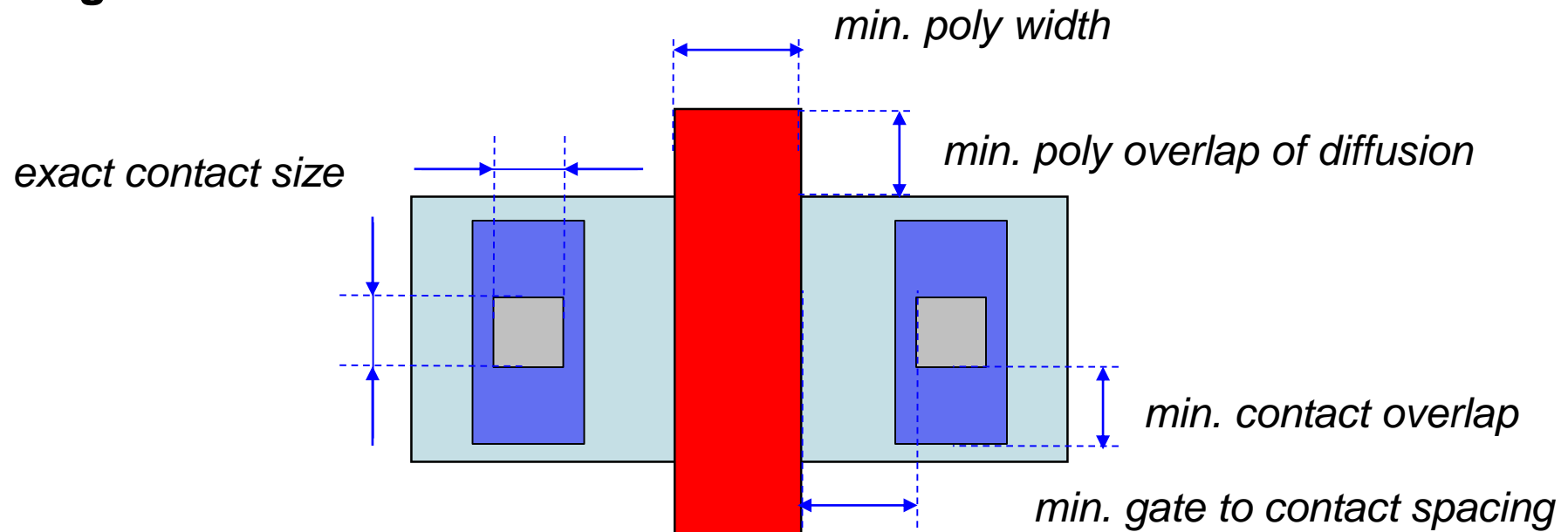
- **Routing** is the physical realization of all those **interconnects between pins** which are connected by an electrical circuit.
- Those interconnects provide both signal and clock/power circuit realization and meet physical (DRC) and electrical (timing, capacitance/transmission, clock, etc) requirements.
- Globally interconnects must provide minimal distortions from circuit operation by ideal connection lines to pass the operation through physical interconnects.

# Design Rules Example

## Resolution



## Alignment



# Optical Proximity Correction (OPC)

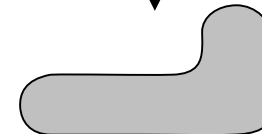
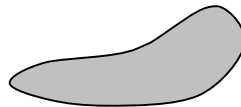
Design



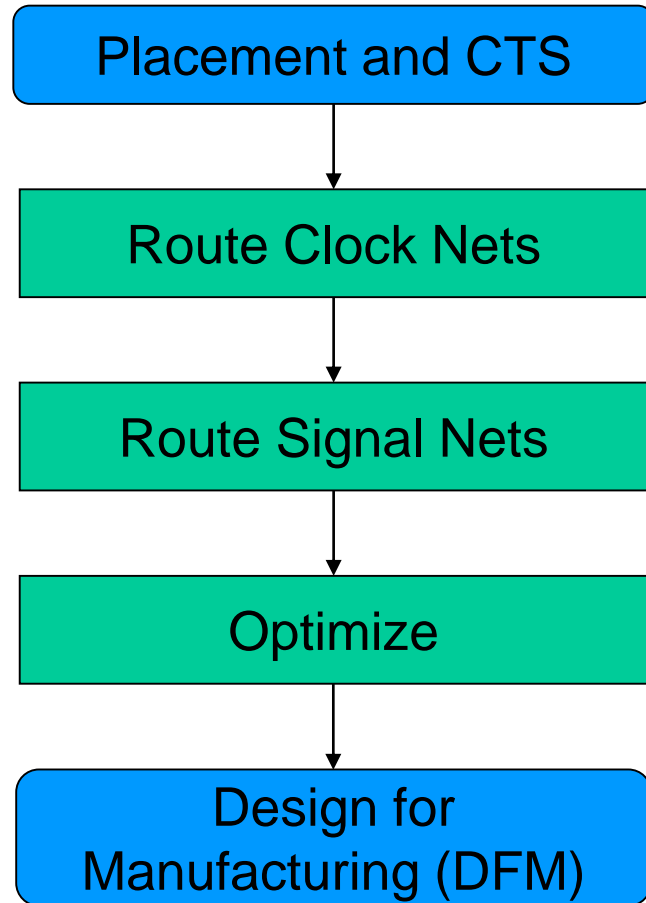
Mask



Wafer

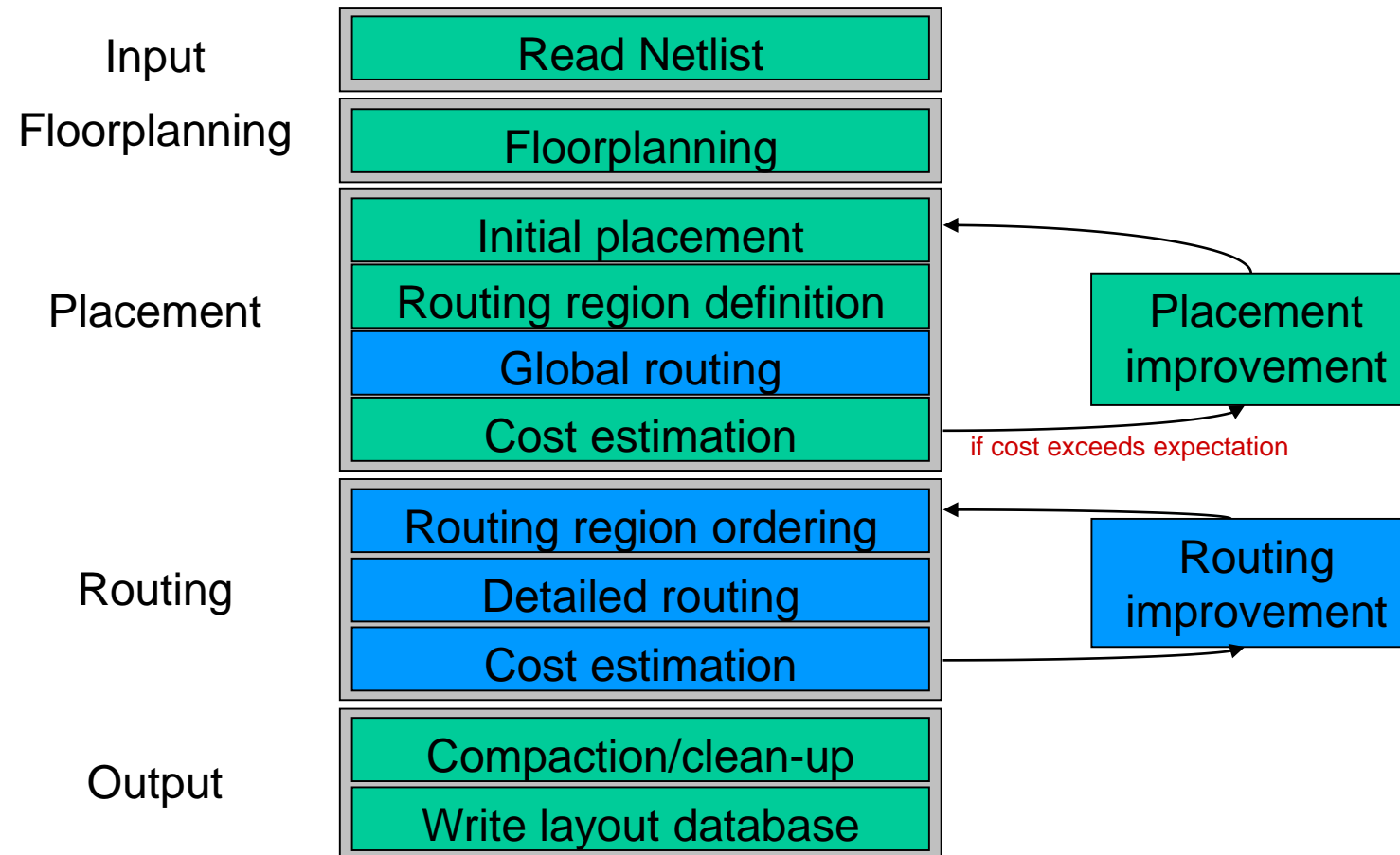


# General Flow of Routing



- In all the design stages, preceding routing (floorplan, placement and CTS), provision of better conditions has been the most important for further routing. This is also called routability.
- Generally IC electrical circuits in the sense of functionality are divided into 3 groups – signal nets, clock nets and power nets.
- In the stage of routing, the physical design of clock nets and power nets are performed (illustrated in figure).

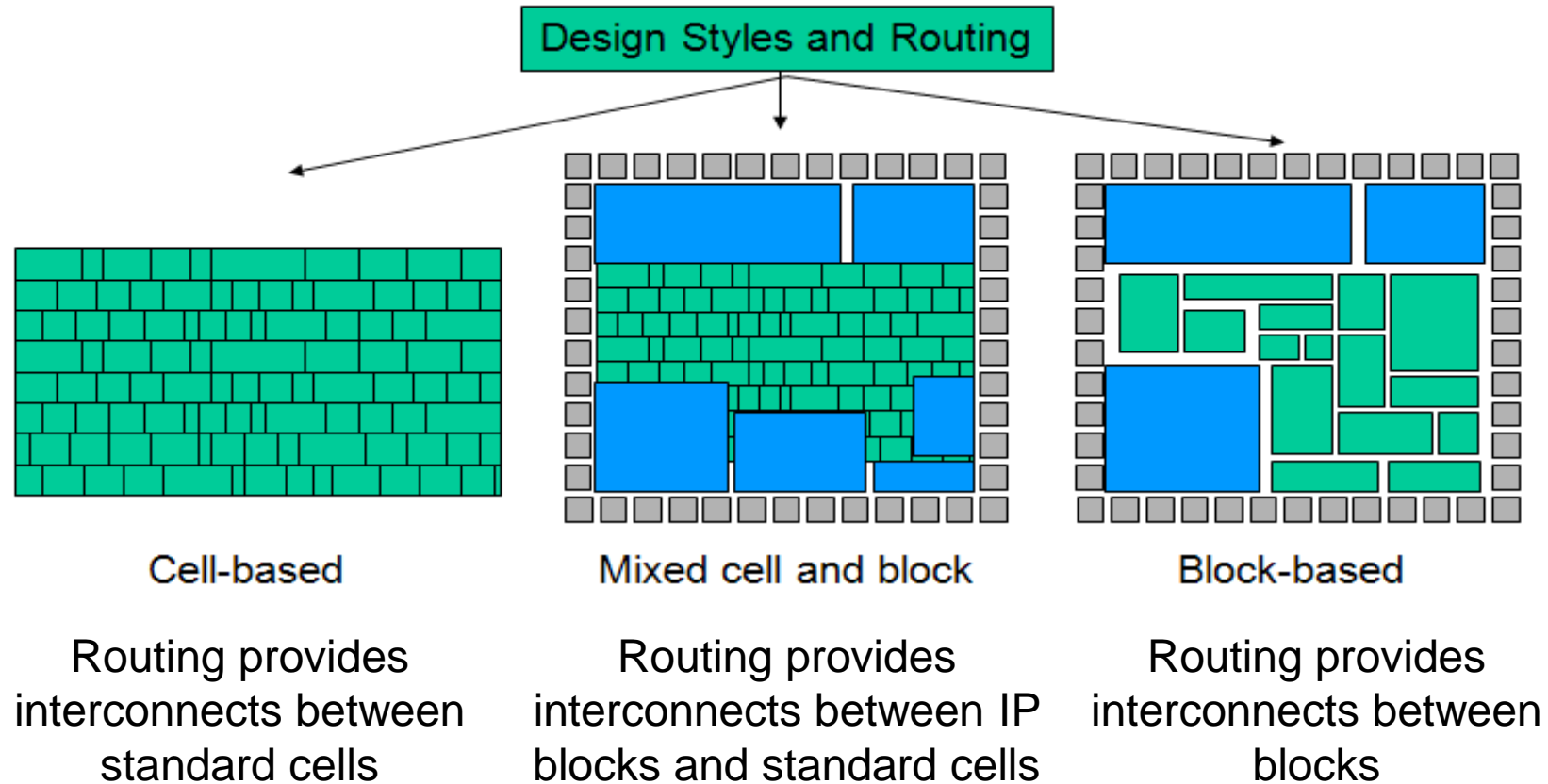
# Routing Steps in Physical Synthesis



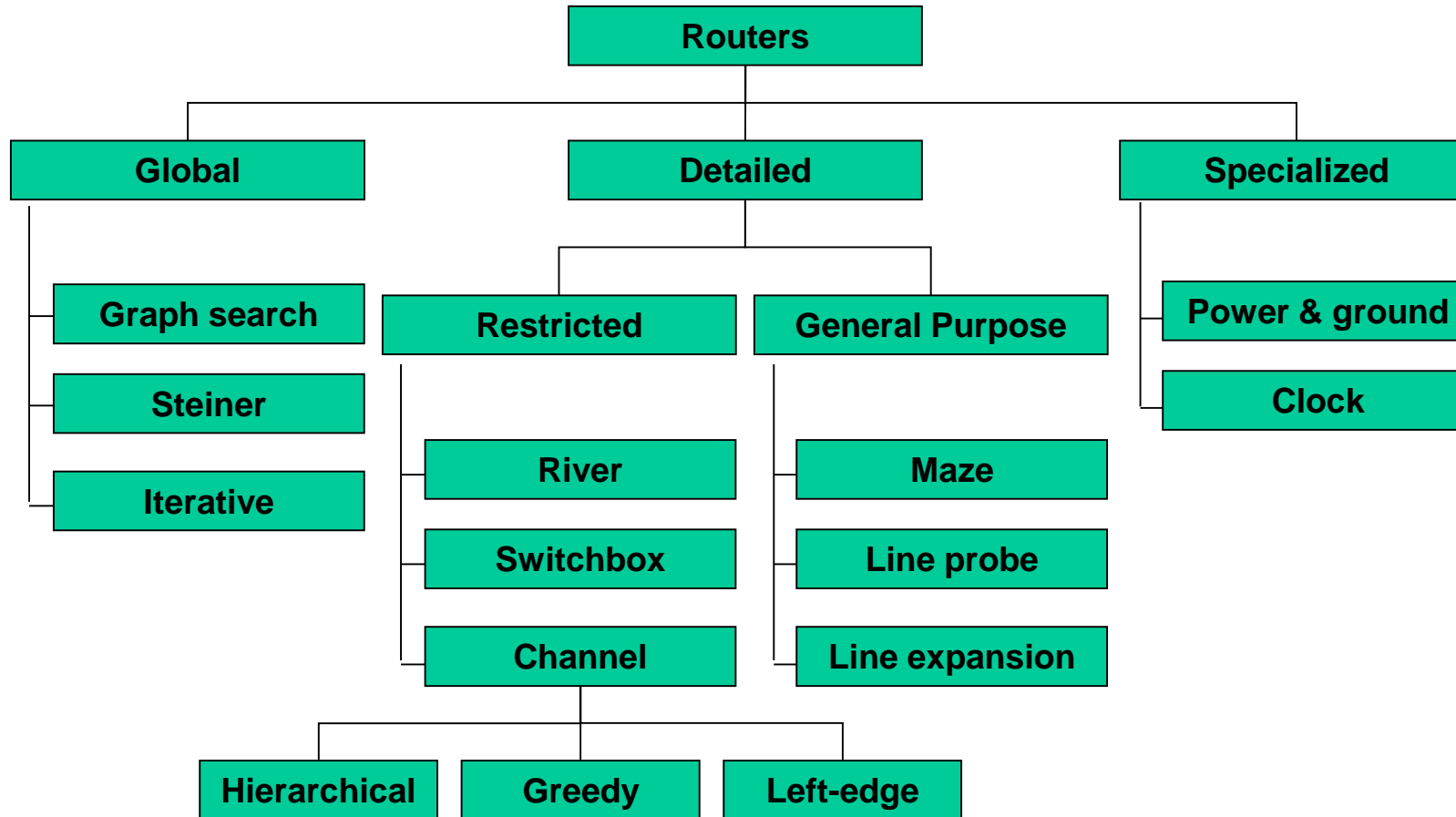
source: Synopsys



# Design Styles and Routing



# Classification of Routing Methods

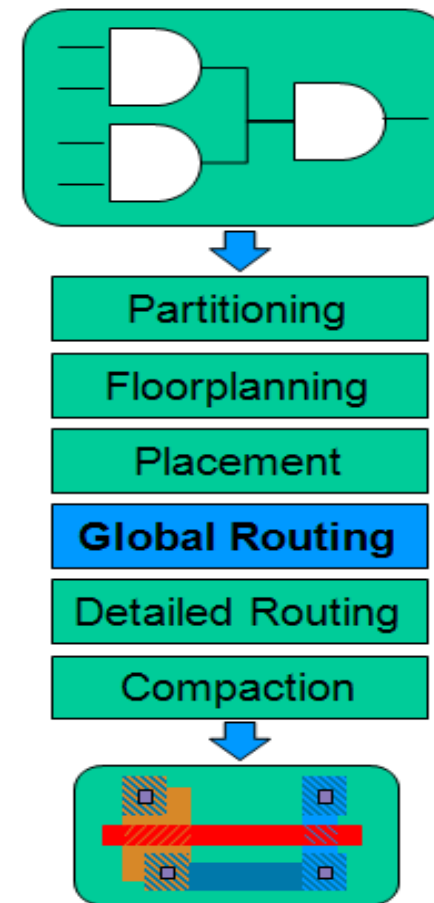
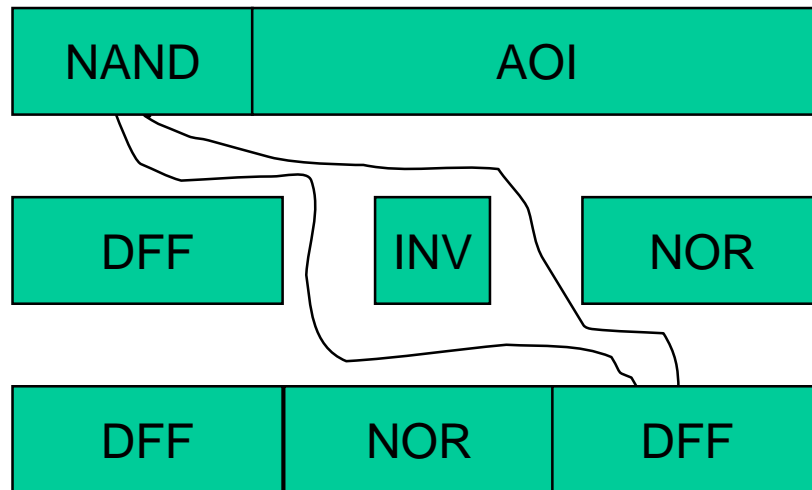


source: Synopsys

# Global Routing

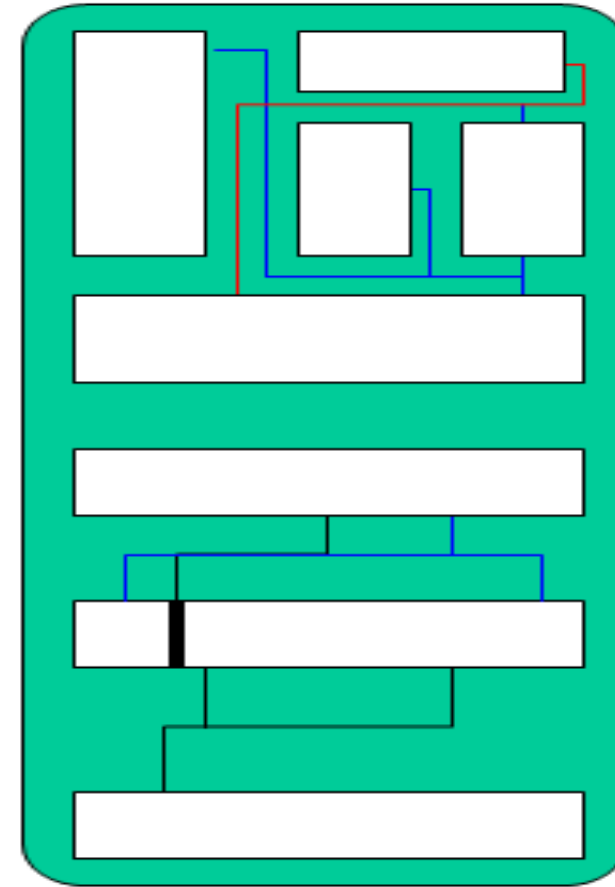
more planning than actual routing

- Determining **overall path** of all routes
  - Picking channels to route through
- Seeking to reduce delay, channel widths



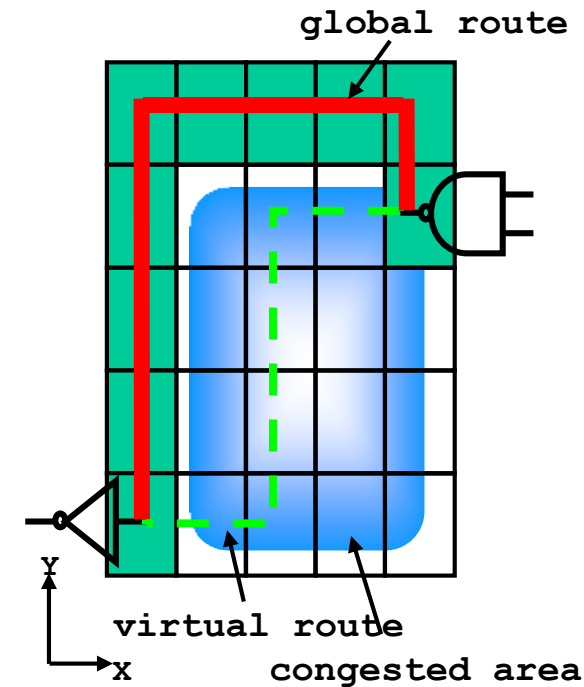
# Global Routing : Inputs and Outputs

- Given
  - Placement of blocks/cells
  - Channel capacities
- Determine
  - Routing topology of each net
- Optimize
  - Maximum number of nets round
  - Minimum routing area
  - Minimum total wirelength



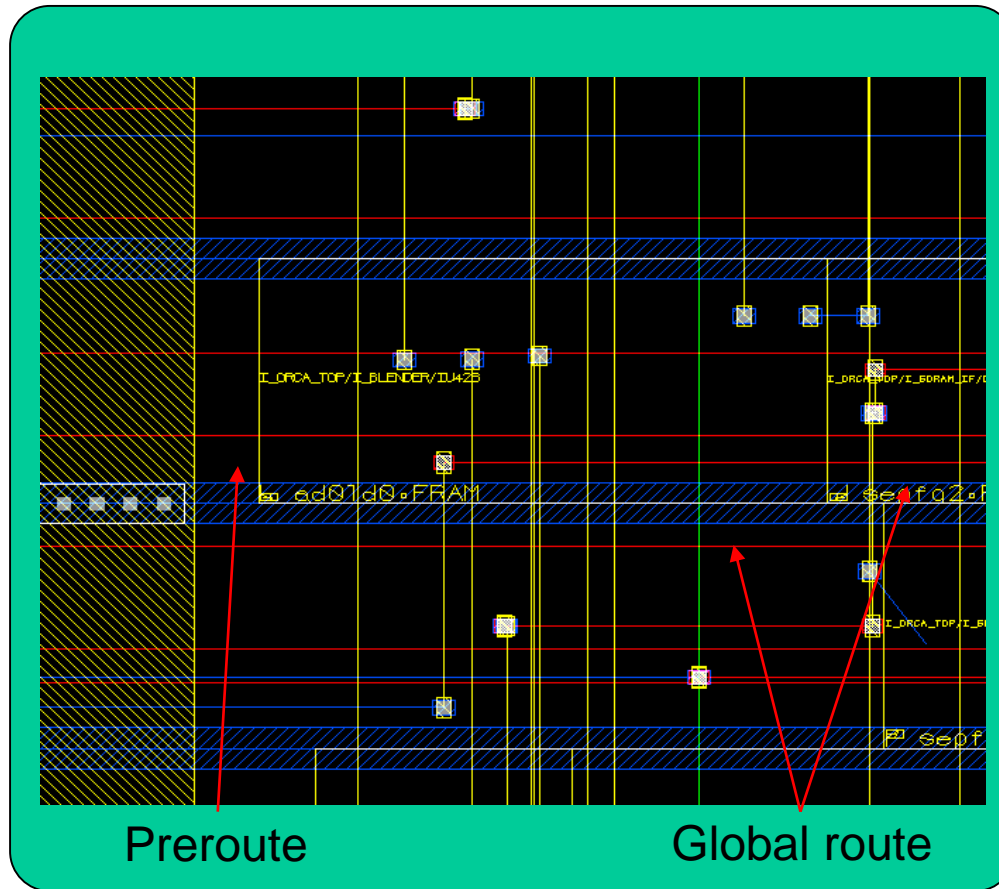
# Route Operations: Global Route

- GR assigns nets to specific metal layers and global routing cells (Gcells)
- GR tries to avoid congested Gcells while minimizing detours
  - Congestion exists when more tracks are needed than available
  - Detours increase wire length (delay)
- GR also avoids
  - P/G (rings/straps/rails)
  - Routing blockages



Metal traces exist after Global Route

# Global Routing : Summary

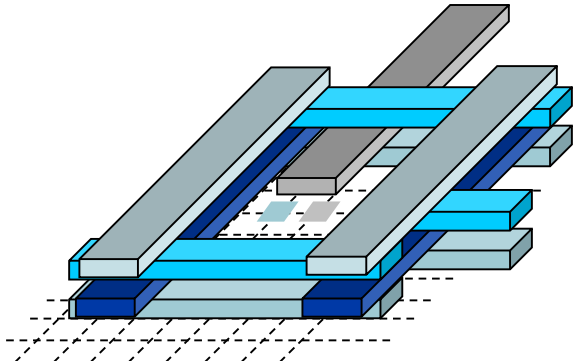


Starting point of routing

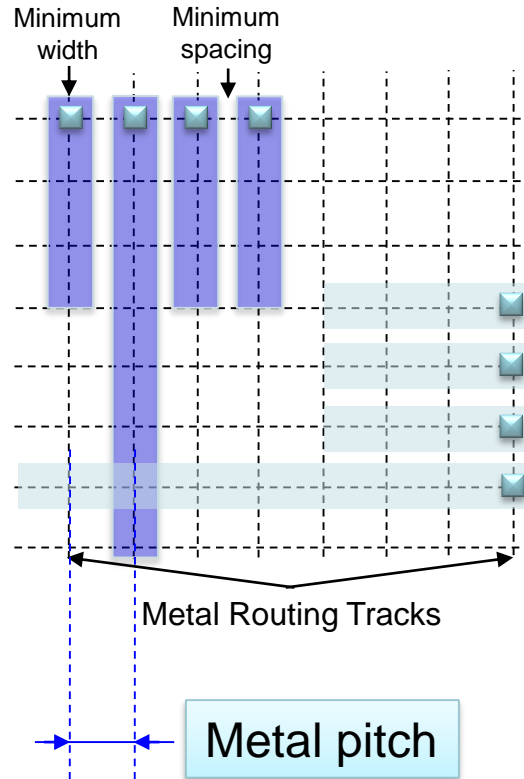
- Global routing is the first stage of routing, and provides global structure for organizing interconnects.
- The importance of global routing increases with the complexity of IC (using IP blocks, and SoC structures).
- Global routing should create good conditions for detailed routing.

# Routing Tracks (Wire Tracks)

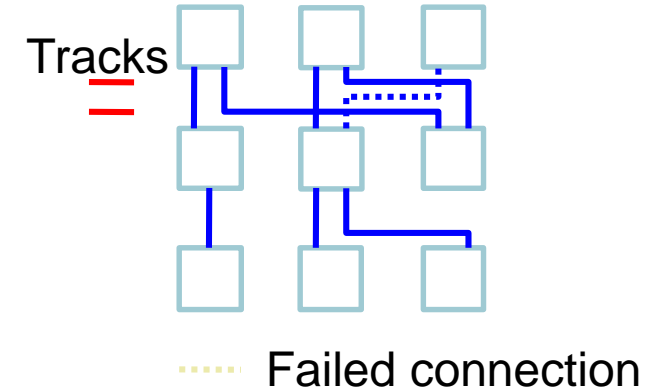
Layers have  
perpendicular  
directions



Routing is done on  
tracks

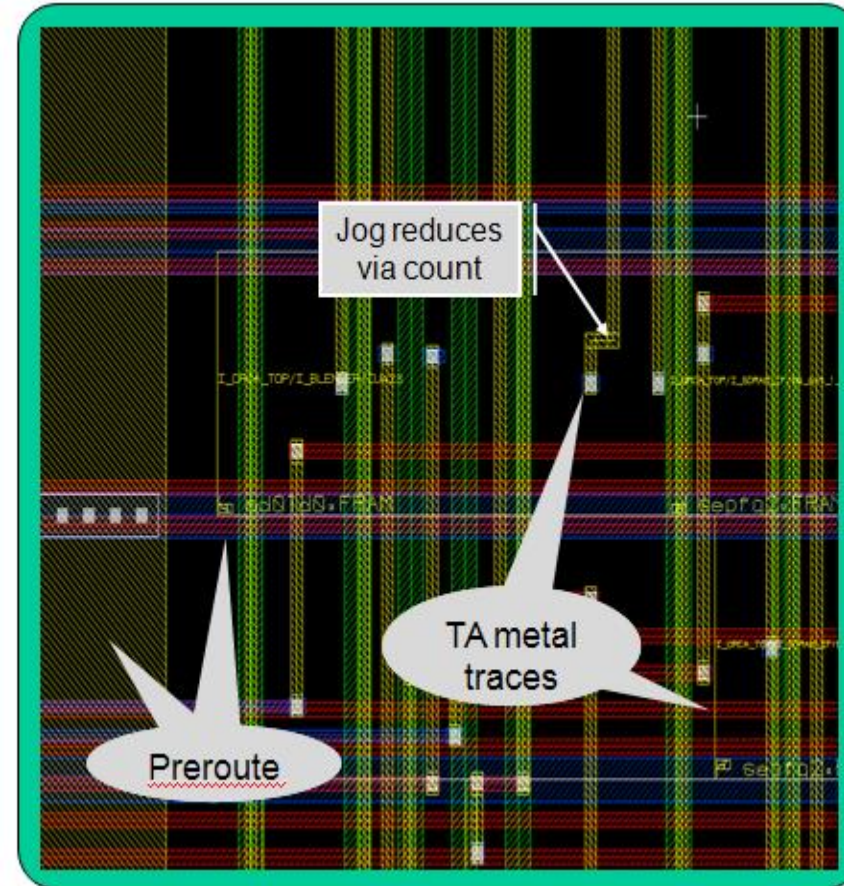


Insufficient number of  
tracks bring  
congestion



# Route Operations : Track Assignment

- Track Assignment (TA):
  - Assigns each net to a specific track and lays down the actual metal traces
- It also attempts to:
  - Make long, straight traces
  - Reduce the number of vias
- TA does not check or follow physical DRC rules



Try to use same metal layer as much as possible

Vias <- higher resistance

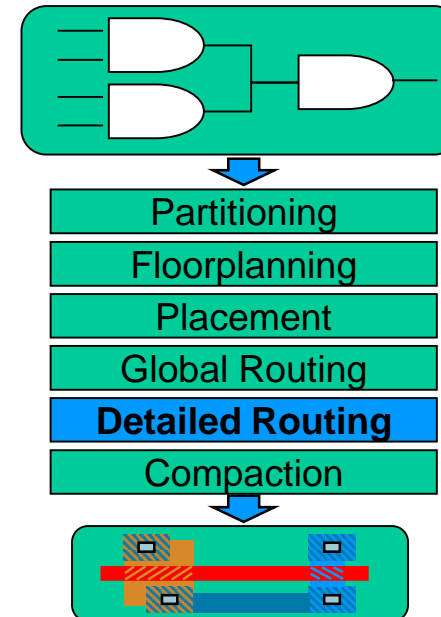
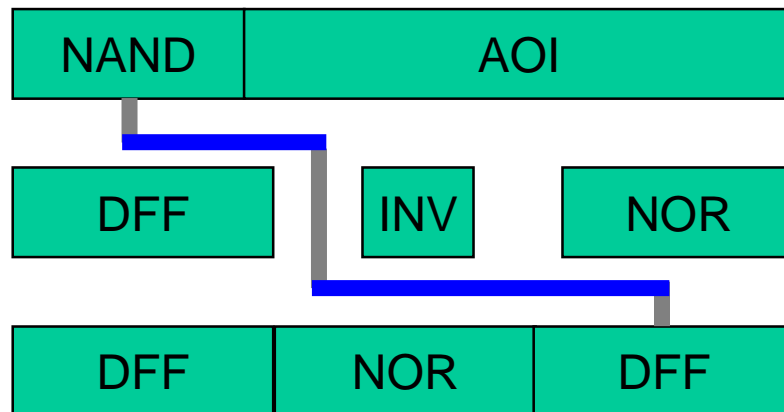
source: Synopsys



# Detailed Routing

Detailed routing **realizes the interconnection** between each connected pair of pins in the region, which has been defined with the result of global routing.

- Determining exactly how each signal is routed through each region
- Seeking to reduce routing area



source: Synopsys

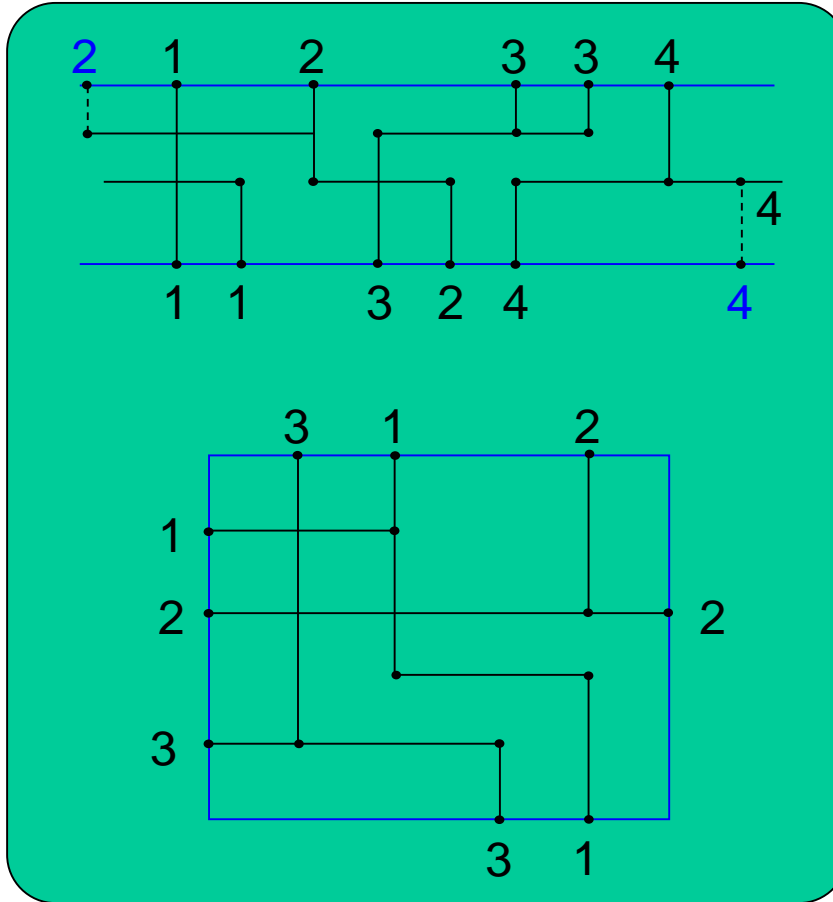
# Detailed Routing: Maze

4	3	2	3	4	5	6	7	8	9	10	11
3	2	1	2	3	4	5	6	7	8	9	10
2	1	A	1		5	6	7	8			
3	2	1	2		6	7	8	9	10	11	12
4	3	2	3							12	13
5	4	3	4		14				B	13	14
6	5			13	14					14	
7	6	7		11	12	13	14				
8	7	8	9	10	11	12	12	14			
9	8	9	10	11	12	13	14				

Maze routing finds a path between source (s) and target (t) in a planar graph

- The basic method of detailed routing is maze routing. The main advantage of maze routing is that it always finds the path with minimal length among all possible paths that connects the two pins.
- The disadvantage is the high machine time demand.

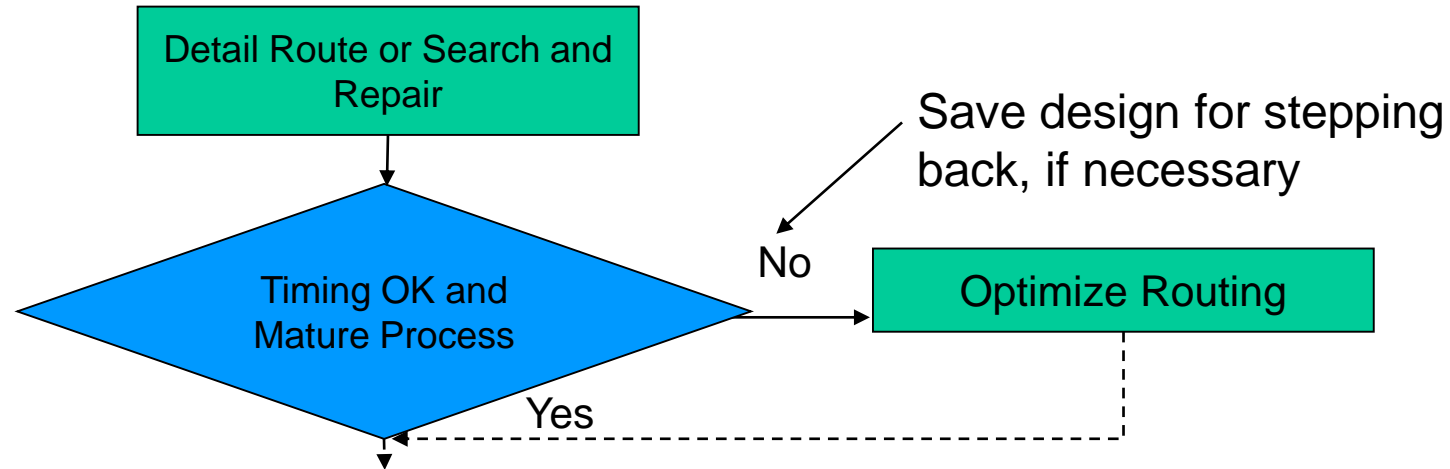
# Detailed Routing: Channel Vs. Switchbox



If the channel routing is a one dimensional problem (interconnects pass only in one direction), then the switchbox routing is a two dimensional problem due to which its solution is more difficult.

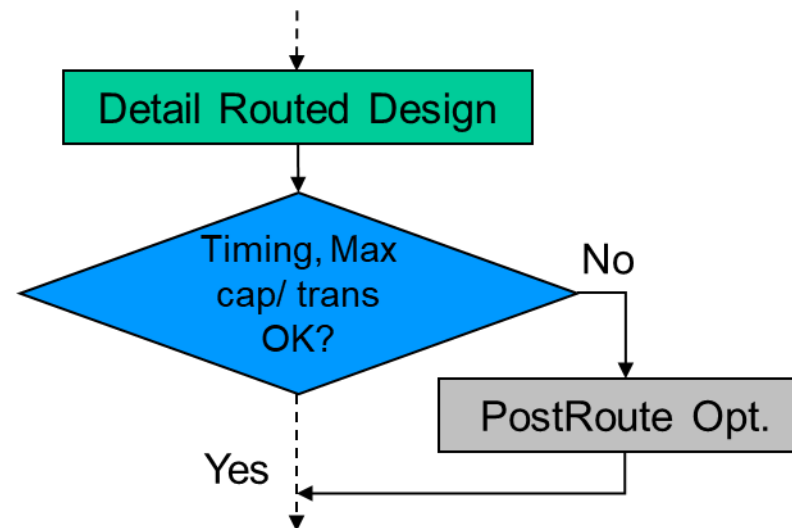
# Route Optimization

- Route optimization can be done by reducing wire length and number of vias, and also by removing unnecessary jogs
- If the process is new or unproven then the reduction in via counts and the increase in long straight routes may improve yield



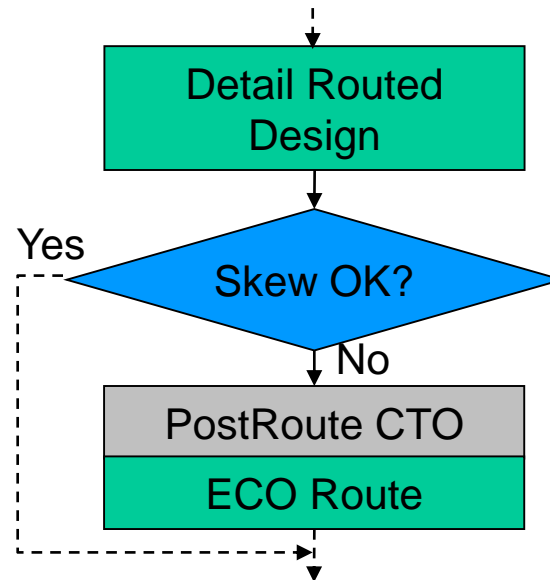
# PostRoute Optimization

- Performing cell sizing, buffer and inverter insertion
- Powerful hold time fixing
- Topology based optimization



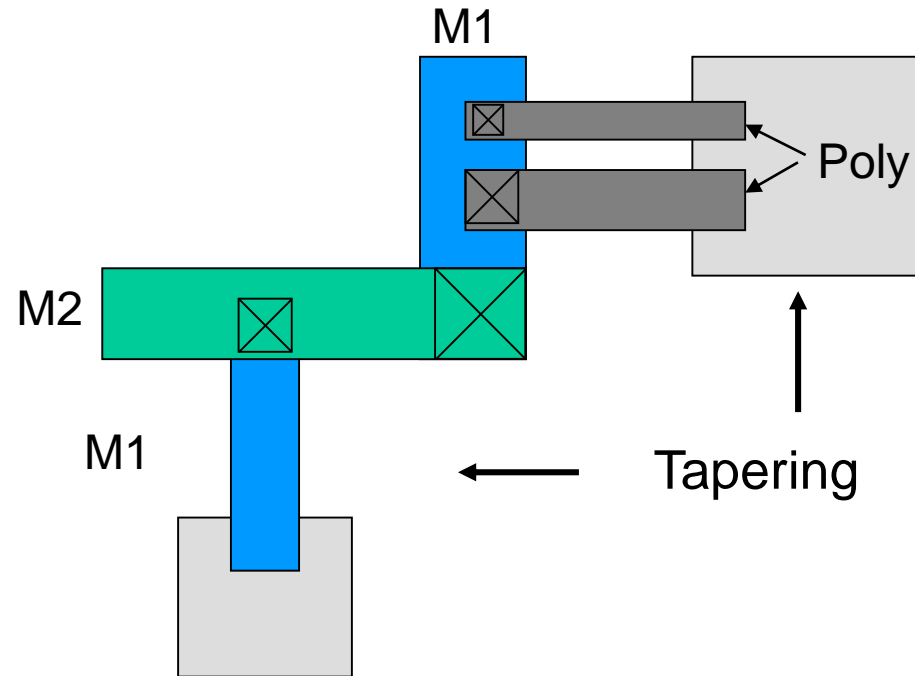
# PostRoute Clock Tree Optimization (CTO)

- Clock skew may have been disturbed by previous routing and route optimization activity
- The CTO step can be used to improve the skew on clock nets



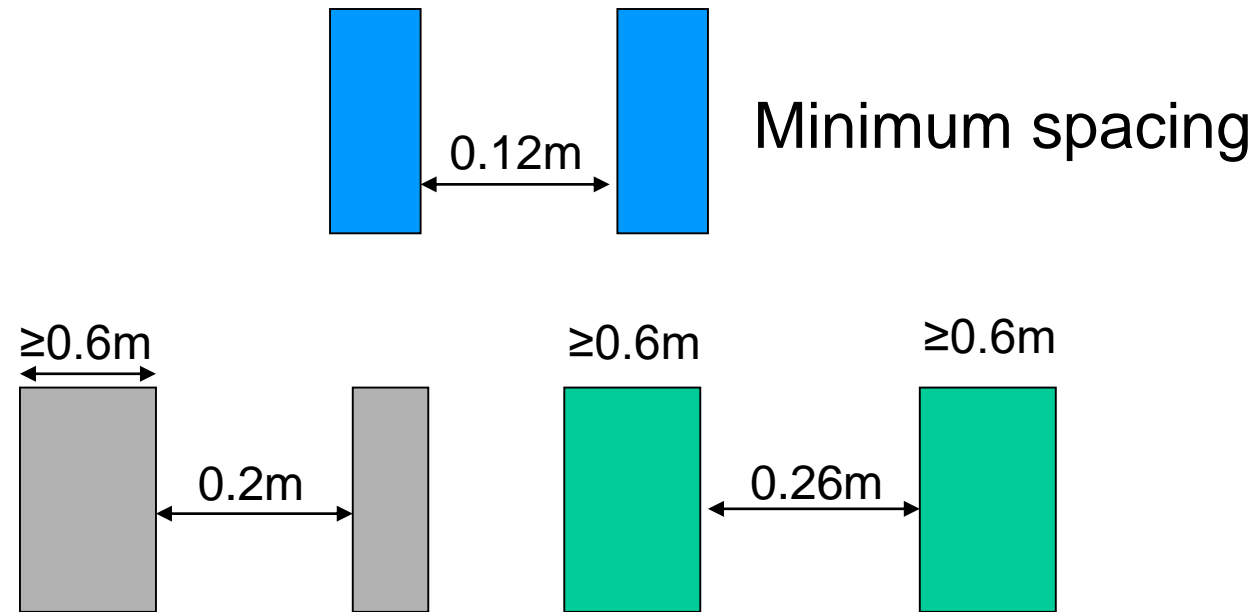
# Detailed Routing Objectives (1)

- Routing completion
- Width and spacing rule
  - Minimum width and spacing
  - Variable width and spacing
    - Connection
    - Net
    - Class of nets
  - Tapering



# Detailed Routing Objectives (2)

Width and spacing rule



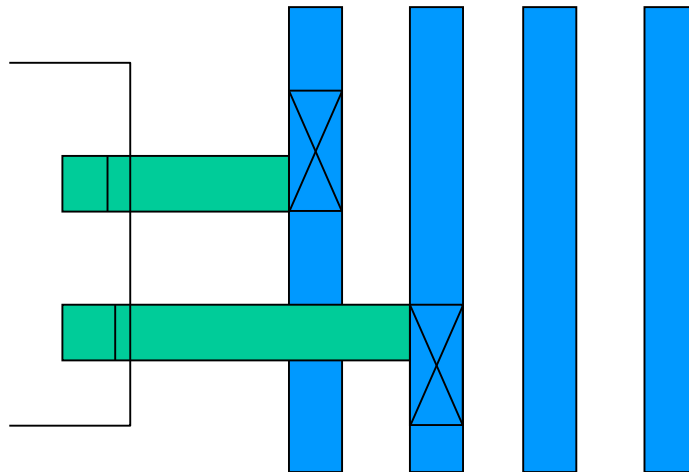
Width-based spacing



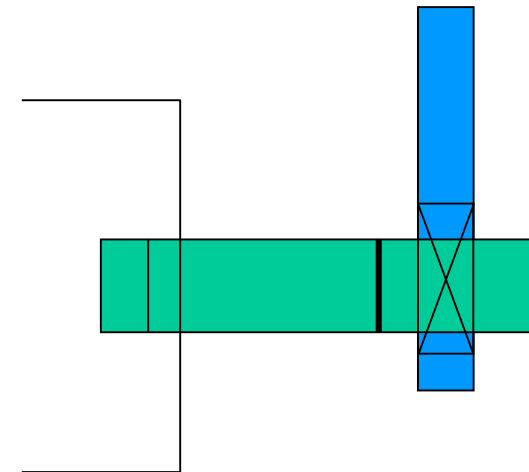
# Detailed Routing Objectives (3)

- Via selection
  - Via array based on wire size or resistance
  - Rectangular via rotation and offset

Rotate and offset horizontal vias

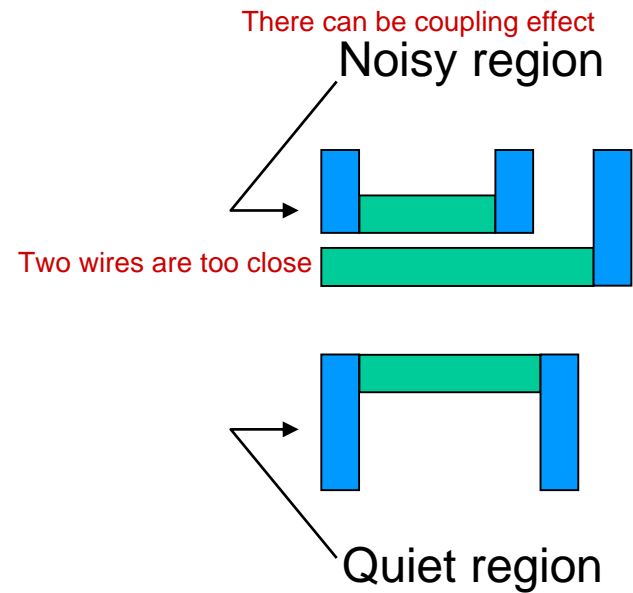


No rotation for a “cross” via



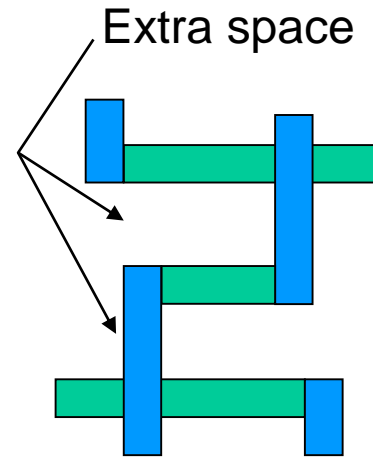
source: Synopsys

# Detailed Routing Objectives (4)

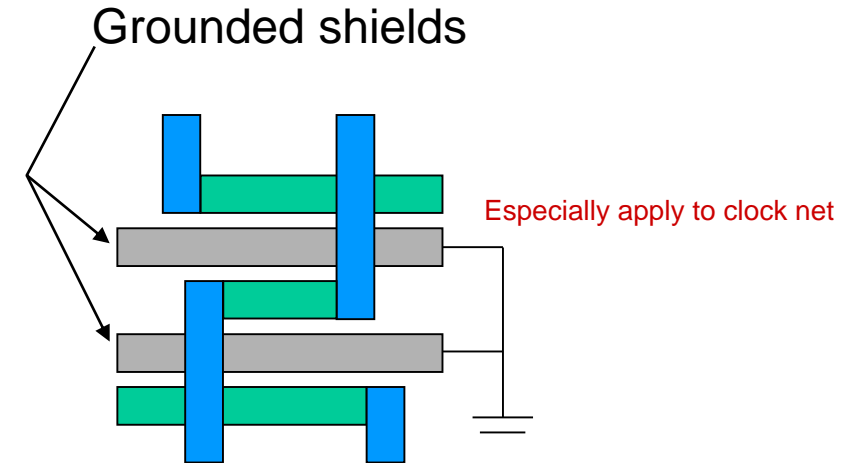


Segregation

Noise-driven



Spacing

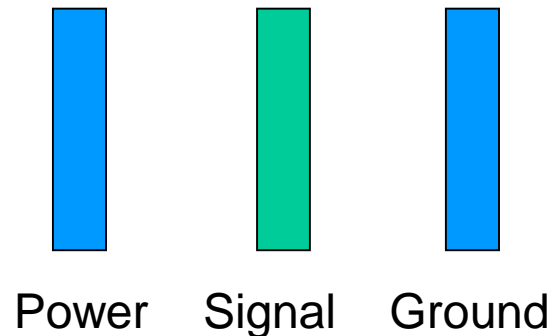


Shielding

# Detailed Routing Objectives (5)

- Shielding
  - Same-layer shielding
  - Adjacent-layer shielding

Same-layer shielding

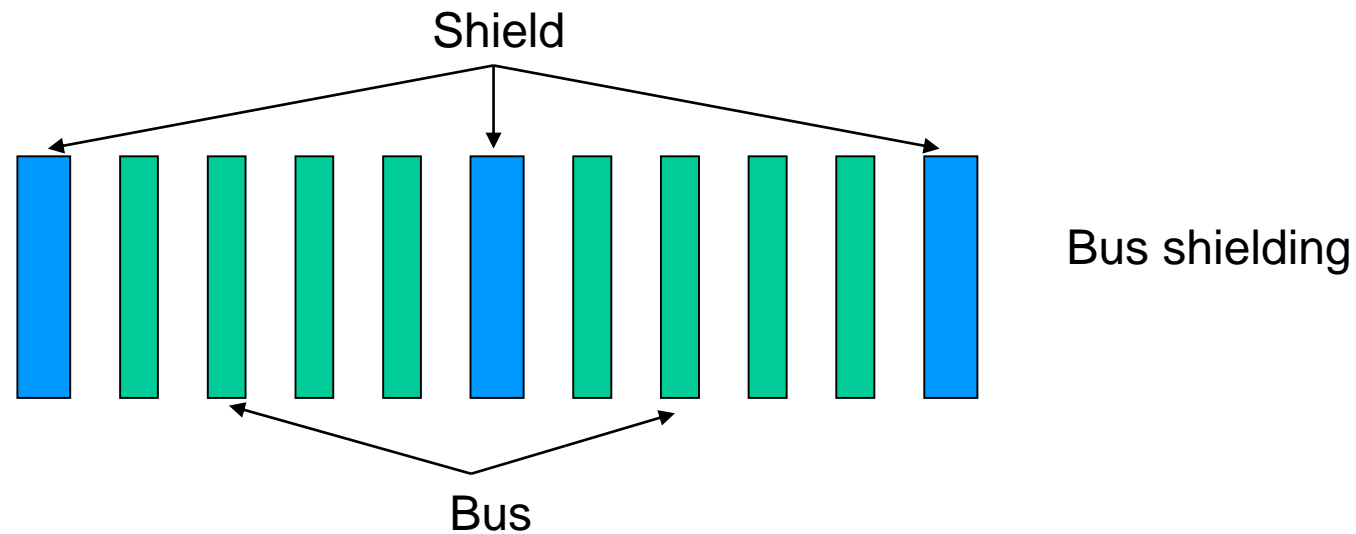


Adjacent-layer shielding



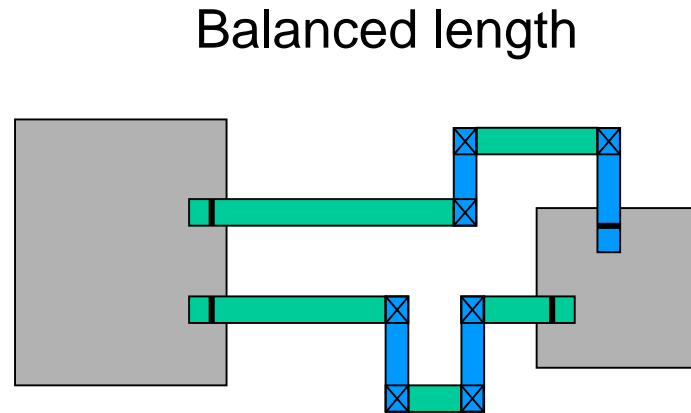
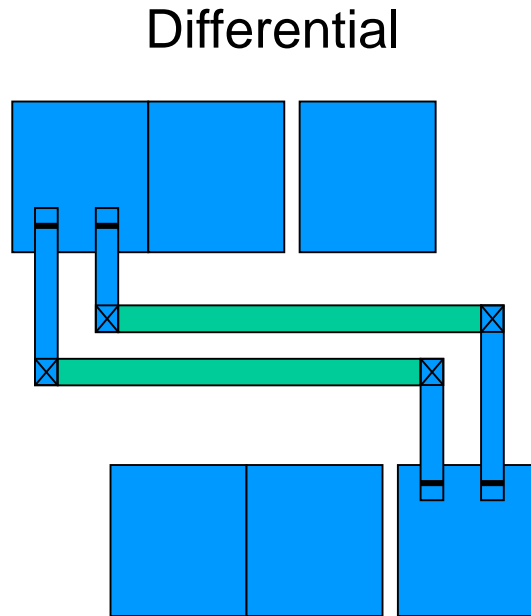
# Detailed Routing Objectives (6)

- Shielding
  - Bus shielding
  - Bus interleaving



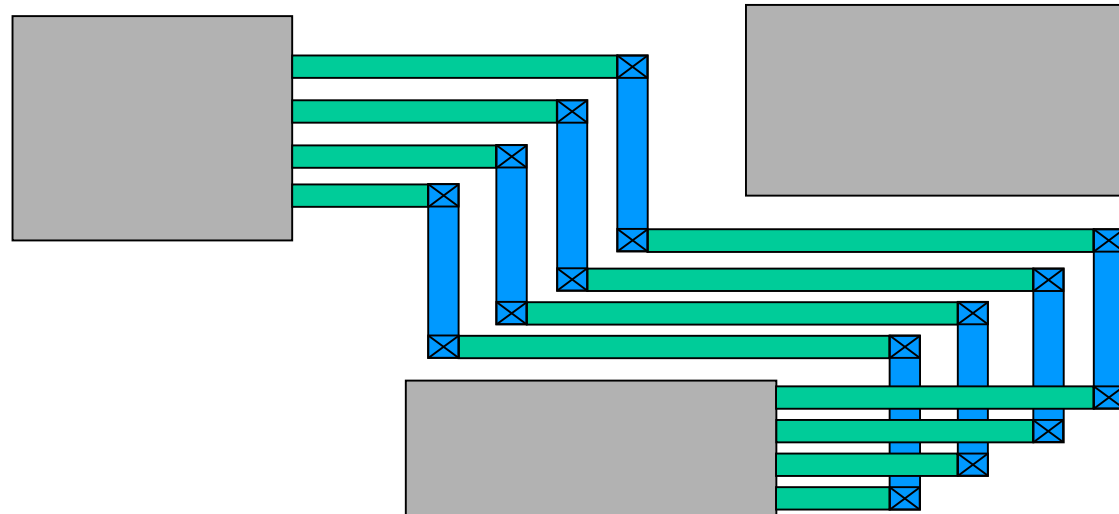
# Detailed Routing Objectives (7)

- Differential pair routing
- Balanced length or capacitance



# Detailed Routing Objectives (8)

Bus routing



The essence is that by changing the metal layer several times (e.g., 4 times) it is possible to route congested parallel buses using 2 metal layers if there are blocks that close the direct path (e.g., the right block above).

# Analysis of the Routing DRC Errors

verify\_route

Uses router DRC engine

verify\_drc

Uses Hercules for DRC

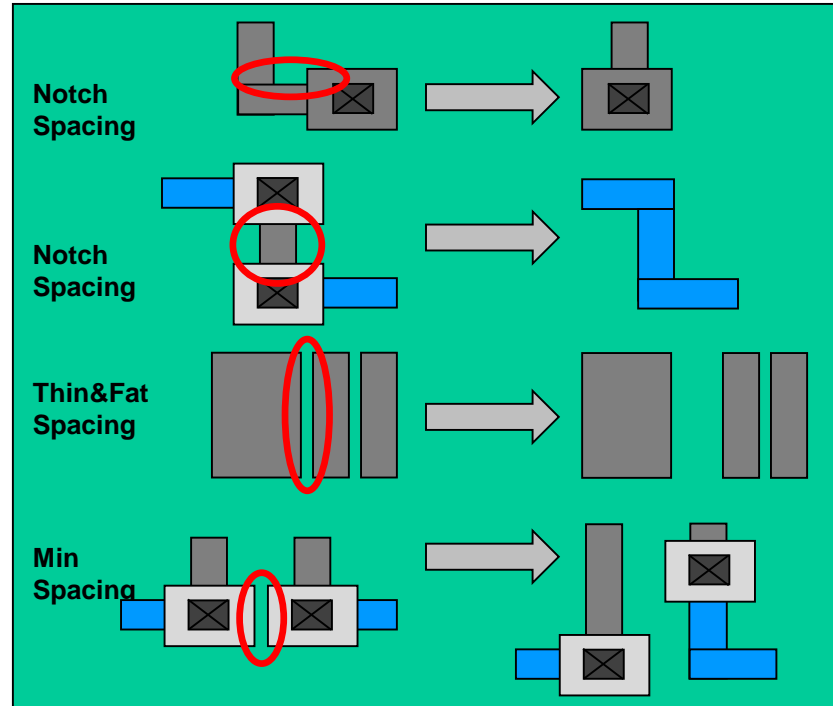
The screenshot shows the IC Compiler layout window with a dense grid of routing lines. An 'Error Browser' dialog is open, displaying a list of errors. The 'Error Type' column shows 'FatWireSpc' with a count of 6425. The 'Count' column shows 36137 for 'route\_opt' and 0 for 'Detail Route'. The 'Error Browser' dialog also shows a list of errors with columns for Id, Type, Layer, and Summary. The 'Id' column shows values from 10000 to 10010. The 'Type' column shows 'FatWireSpcMet4'. The 'Layer' column shows 'Met4 F...'. The 'Summary' column shows 'Met4 F...'. The 'Error Browser' dialog also has a 'Show in layout' section with options for 'None', 'All', and 'Selected'. The 'Zoom to selected' checkbox is checked, and the 'Scale' is set to 2.0.

Error Type	Count
route_opt	36137
Detail Route	0
DRC	36137
FatWireSpc	6425
MinArea	12486
MinWidth	135
Overlap	4253
Spacing	12838

Id	Type	Layer	Summary
10000	FatWireSpcMet4	Met4 F...	Met4 F...
10001	FatWireSpcMet4	Met4 F...	Met4 F...
10002	FatWireSpcMet4	Met4 F...	Met4 F...
10003	FatWireSpcMet4	Met4 F...	Met4 F...
10004	FatWireSpcMet4	Met4 F...	Met4 F...
10005	FatWireSpcMet4	Met4 F...	Met4 F...
10006	FatWireSpcMet4	Met4 F...	Met4 F...
10007	FatWireSpcMet4	Met4 F...	Met4 F...
10008	FatWireSpcMet4	Met4 F...	Met4 F...
10009	FatWireSpcMet4	Met4 F...	Met4 F...
10010	FatWireSpcMet4	Met4 F...	Met4 F...

source: Synopsys

# Fixing DRC Violations

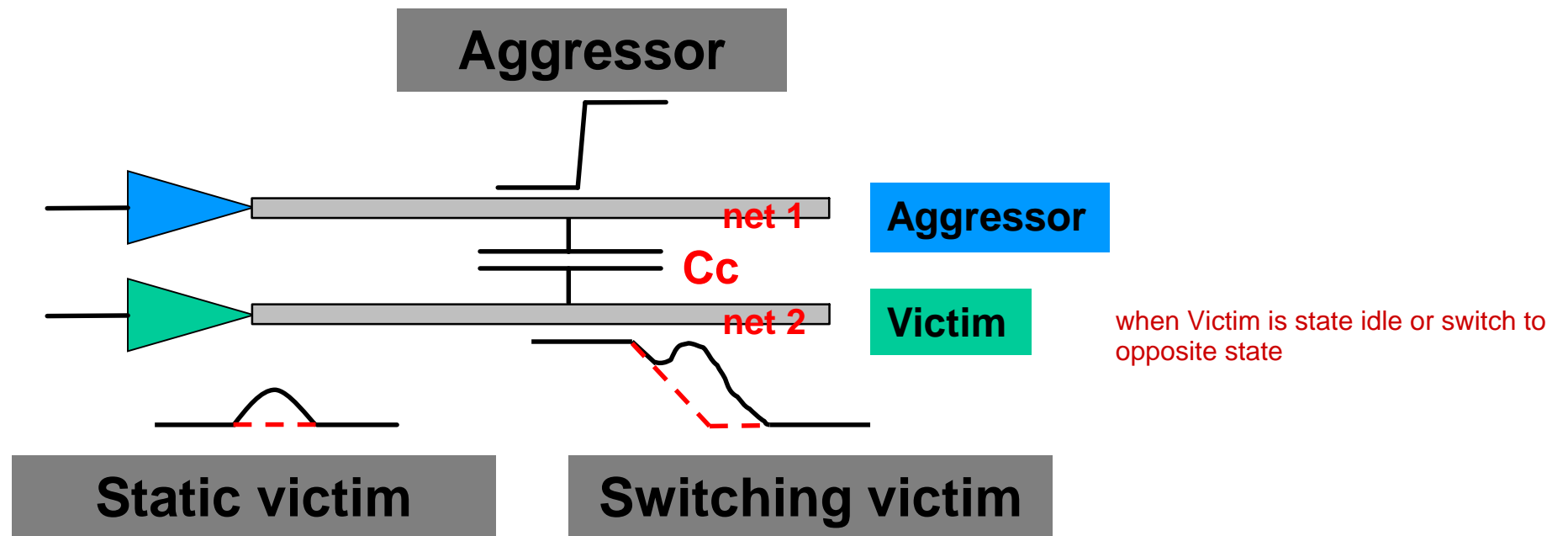


Use route\_opt (fixes timing as well):  
`route_opt -incremental`



# Crosstalk (Xtalk)

**Crosstalk** is the transfer of a voltage transition from one switching net (aggressor) to another static or switching net (victim) through a coupling capacitance ( $C_c$ )

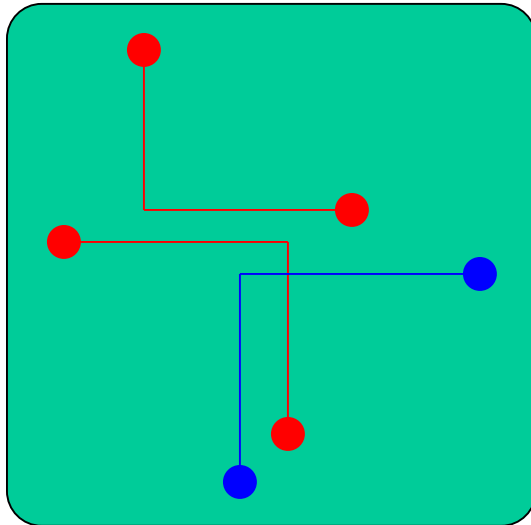


source: Synopsys

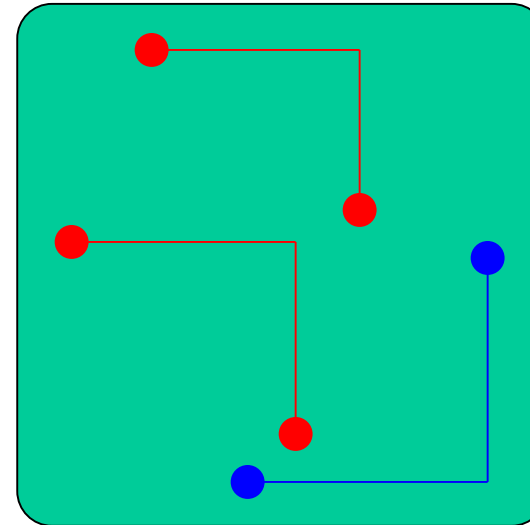
# Coupling-Free Routing (CFR)

- Coupling-free Routing means there is a single bend layout for every net such that no two routes couple

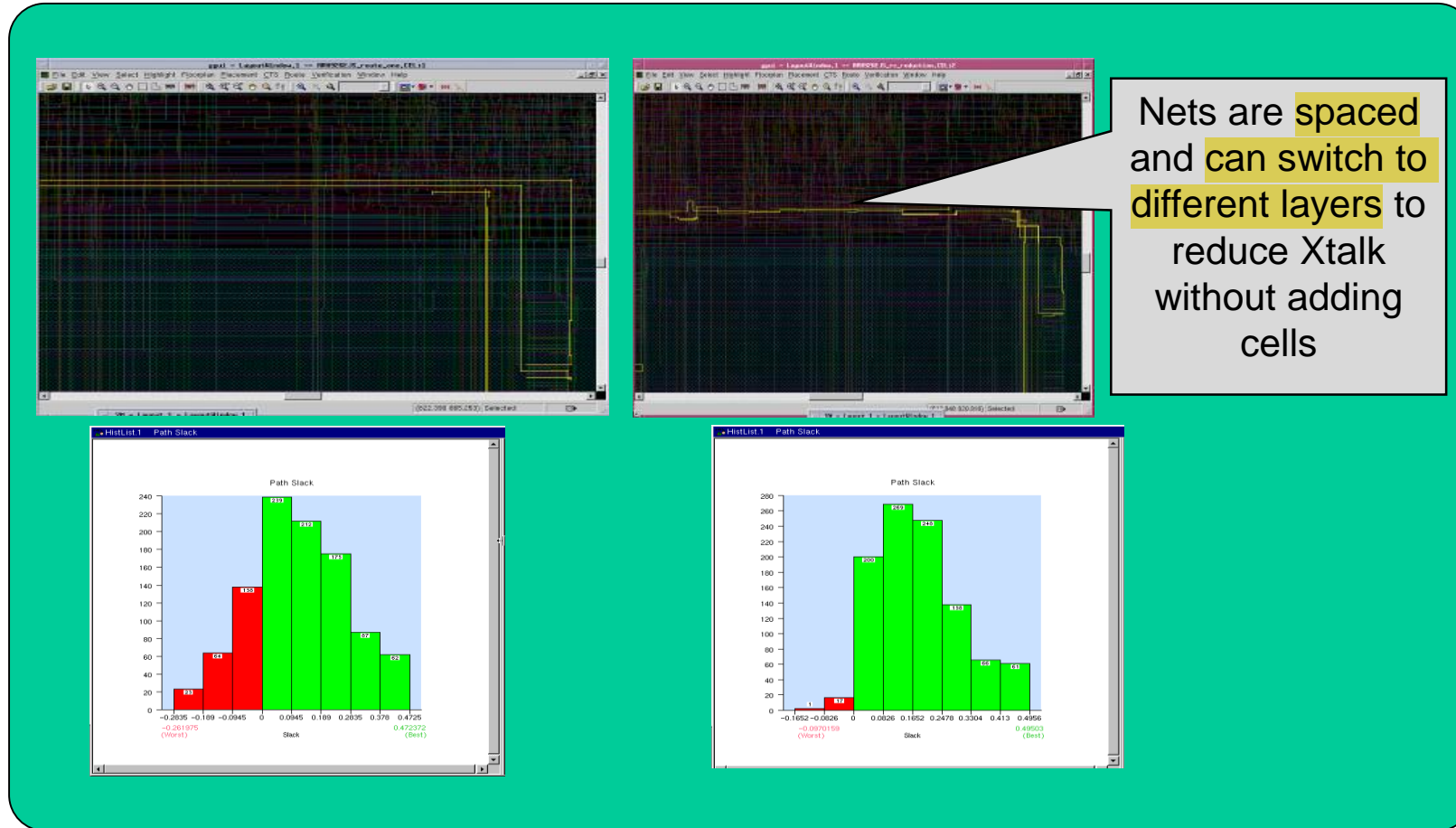
Coupled layout



Coupling-free layout

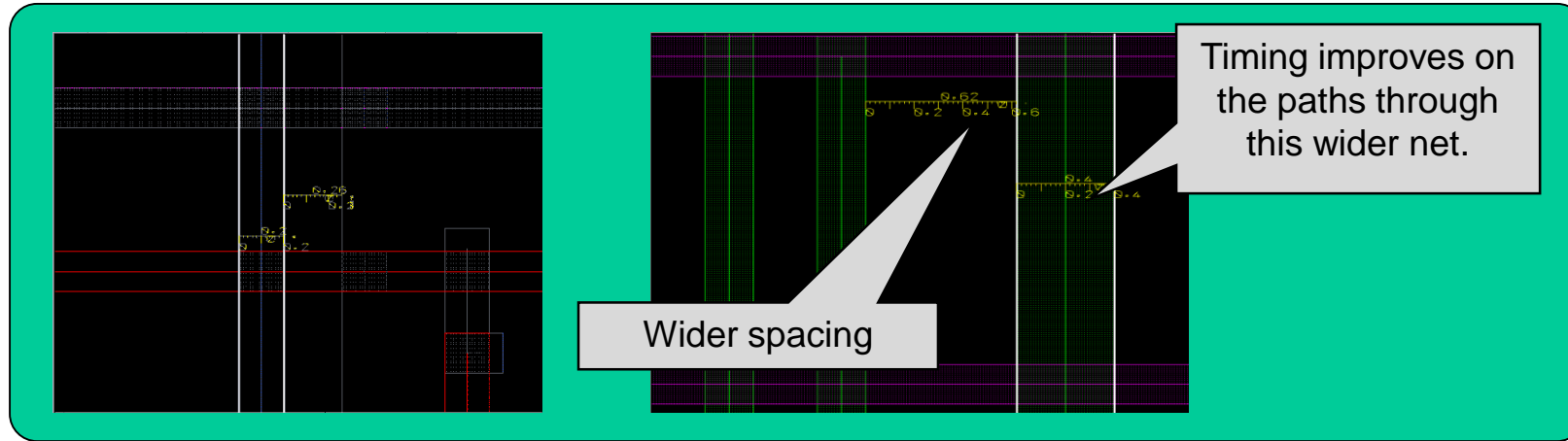


# Xtalk-Reduction at Work



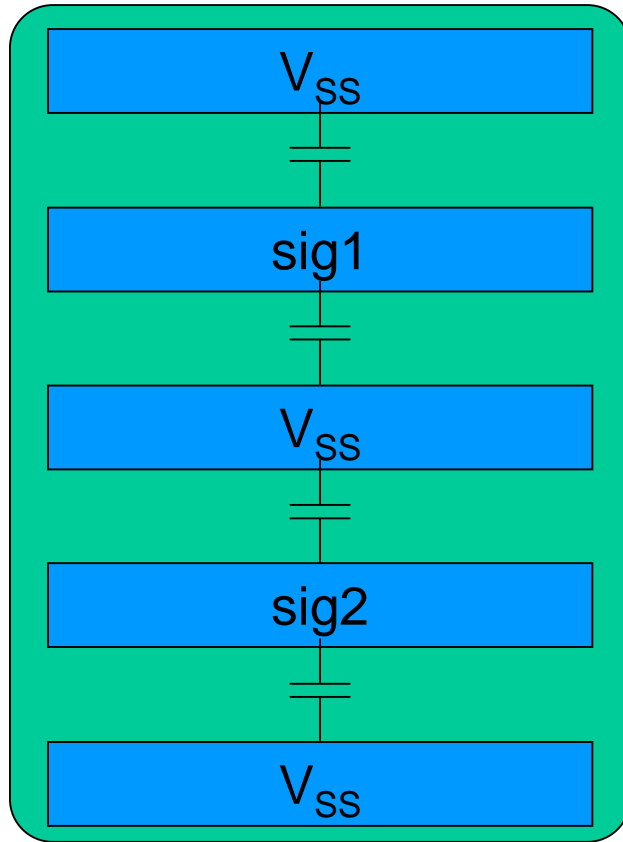
source: Synopsys

# Wire Sizing at Work



- Critical wire has been made wider to solve a timing violation. Since  $R$  is reduced, it can benefit the timing. The wider spacing helps crosstalk.
- Use carefully since too many NDRs can make the design unroutable.

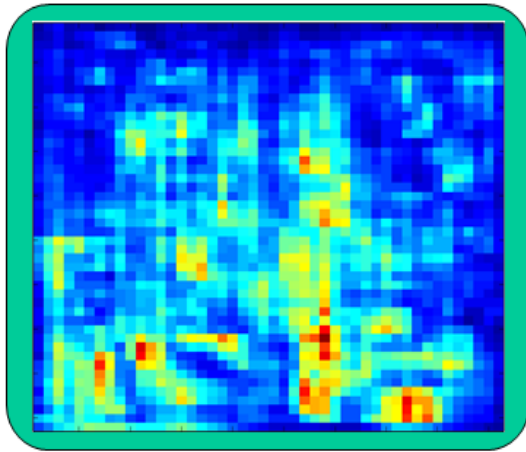
# Crosstalk and Physical Synthesis: Ground Wires



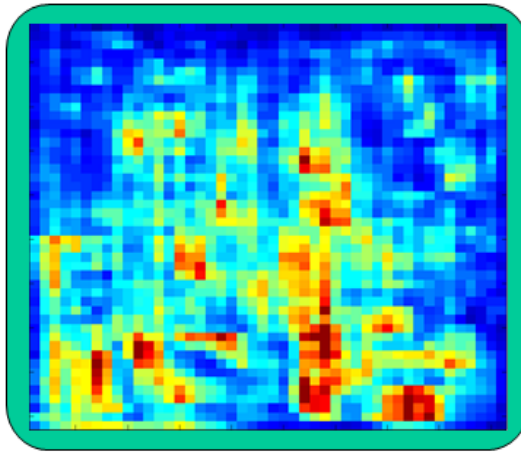
- In order to isolate signal nets passing through different layers and to reduce crosstalk, ground wires are added (shown in figure) between signal wires.
- $V_{ss}$  can be used to distribute power as long as the power line is relatively stable.

# Congestion, Coupling and Noise Maps

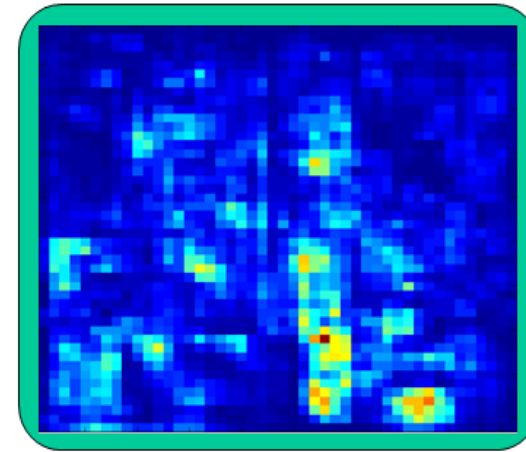
Congestion map



Coupling cap map



Noise map



Congestion map not necessarily matches to coupling capacitance map

Coupling is more pervasive than congestion

Coupling cap map is different from noise map

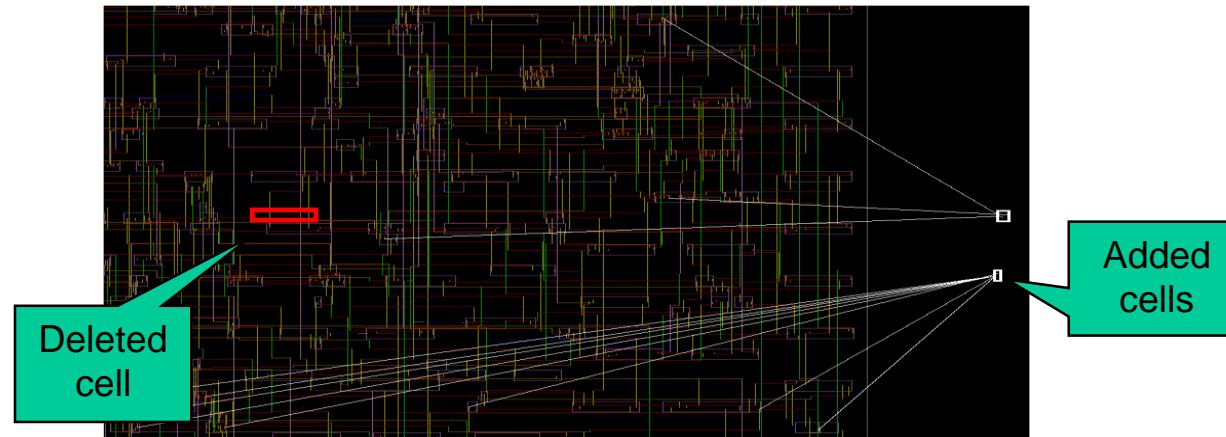
Noise also depends on electrical properties ( $R_d$  for victim net)

# ECO: Engineering Change Order

Fix things in the last minute...

# ECOs: Making Changes Late in the Flow

- “ECO” is an old term which stands for “Engineering Change Order”.
- In the early days of circuit design, if a change has to be made in the design which was already defined or specified, then an “Engineering Change Order” form has to be filled out and signed before making the change.



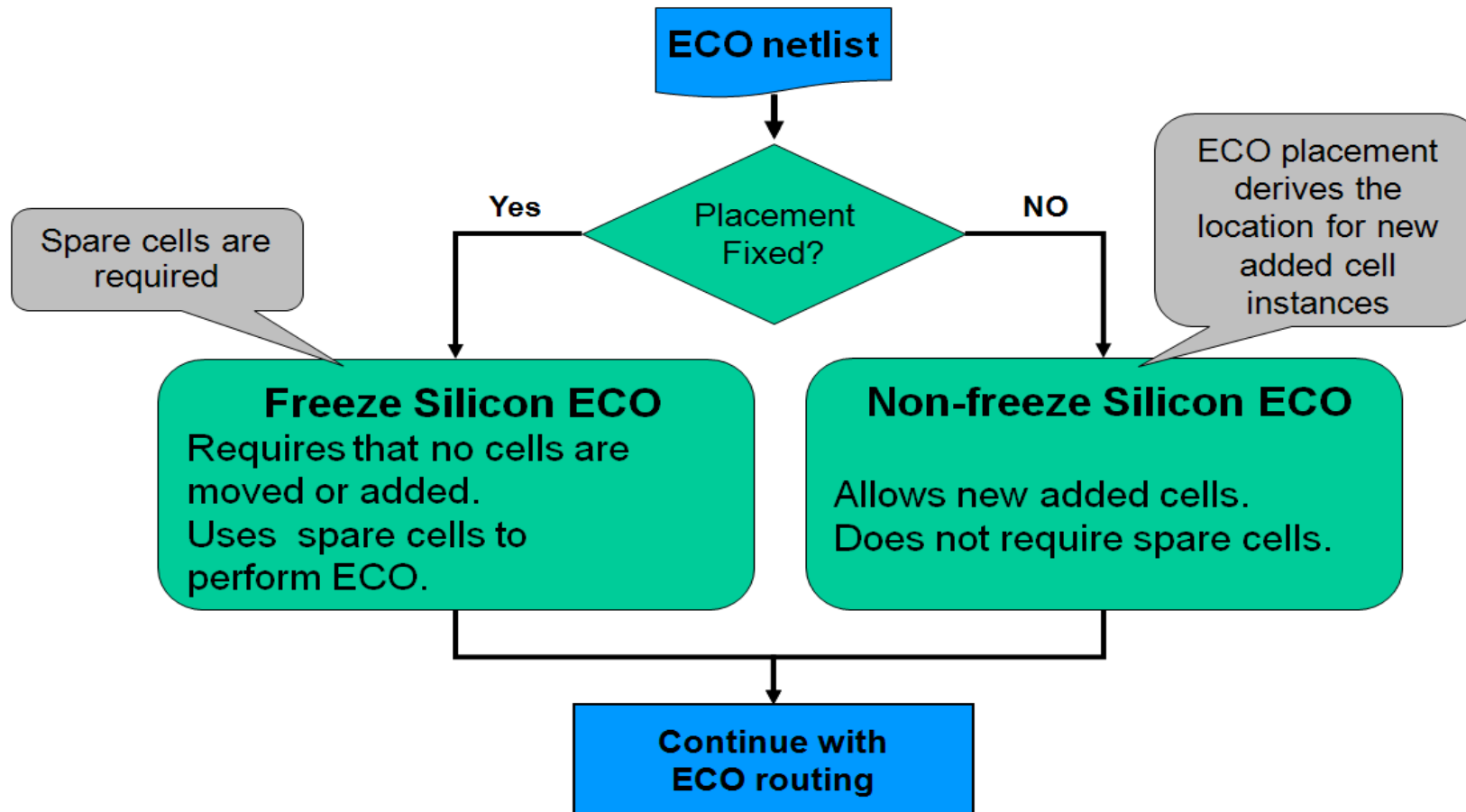
**Functional changes occur late in the design cycle**



# Types of ECO

- Functional ECO
  - Functional bug that was discovered in the last minute
- Timing ECO
  - ECOs that are required to fix timing violations
  - E.g. Swap cells, move to a different location
- Power ECO
  - ECOs that are required to fixing power violations
- ECO cells
  - Special cells that designed so it can later be configured to perform certain functions

# Two Types of ECO Flows



# ECO Flows

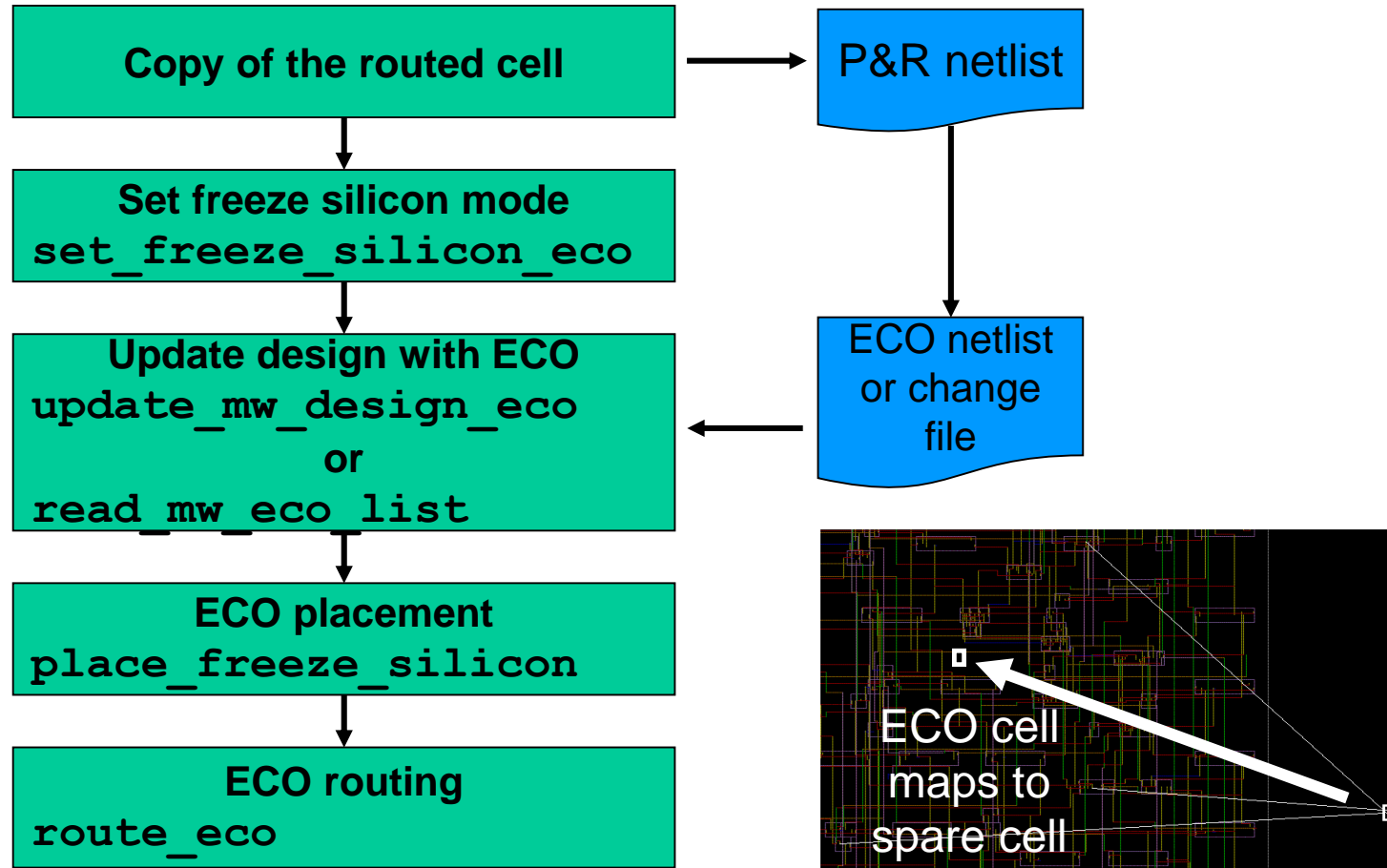
## ■ Non-Freeze silicon ECO

- Pre-tapeout - no restriction on placement or routing
- Minimal disturbances to the existing layout
- ECO cells are placed close to their optimal locations

## ■ Freeze silicon ECO

- Post-tapeout - metal masks change only using previously inserted spare cells
- Cell placement remains unchanged
- ECO cells are mapped to spare cells that are closest to the optimal location
- Deleted cells become spare cells

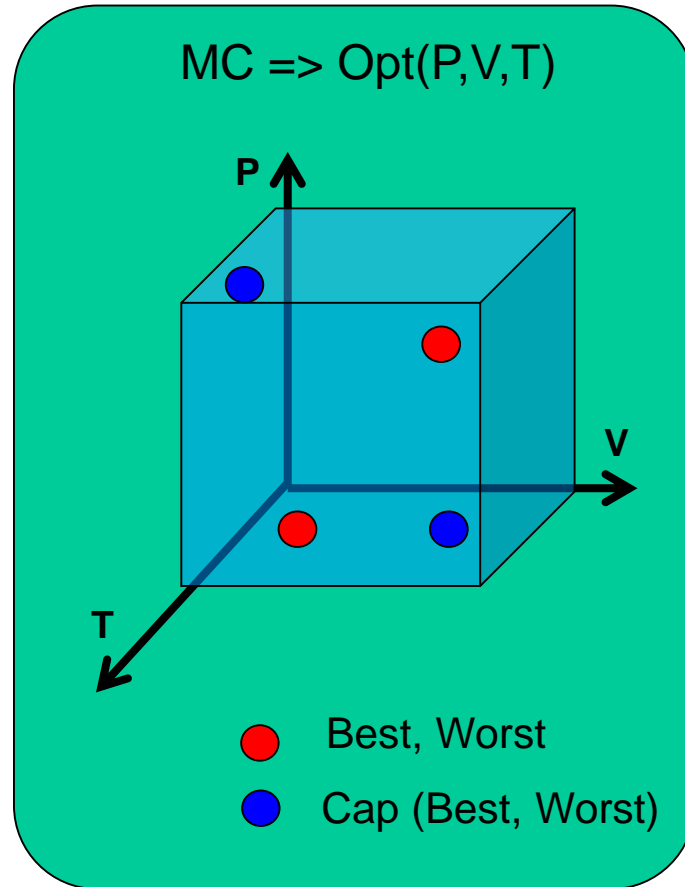
# Freeze Silicon ECO: Metal Change Only



# Multi Scenario Optimization

How to ensure that the chip works under multiple corners...

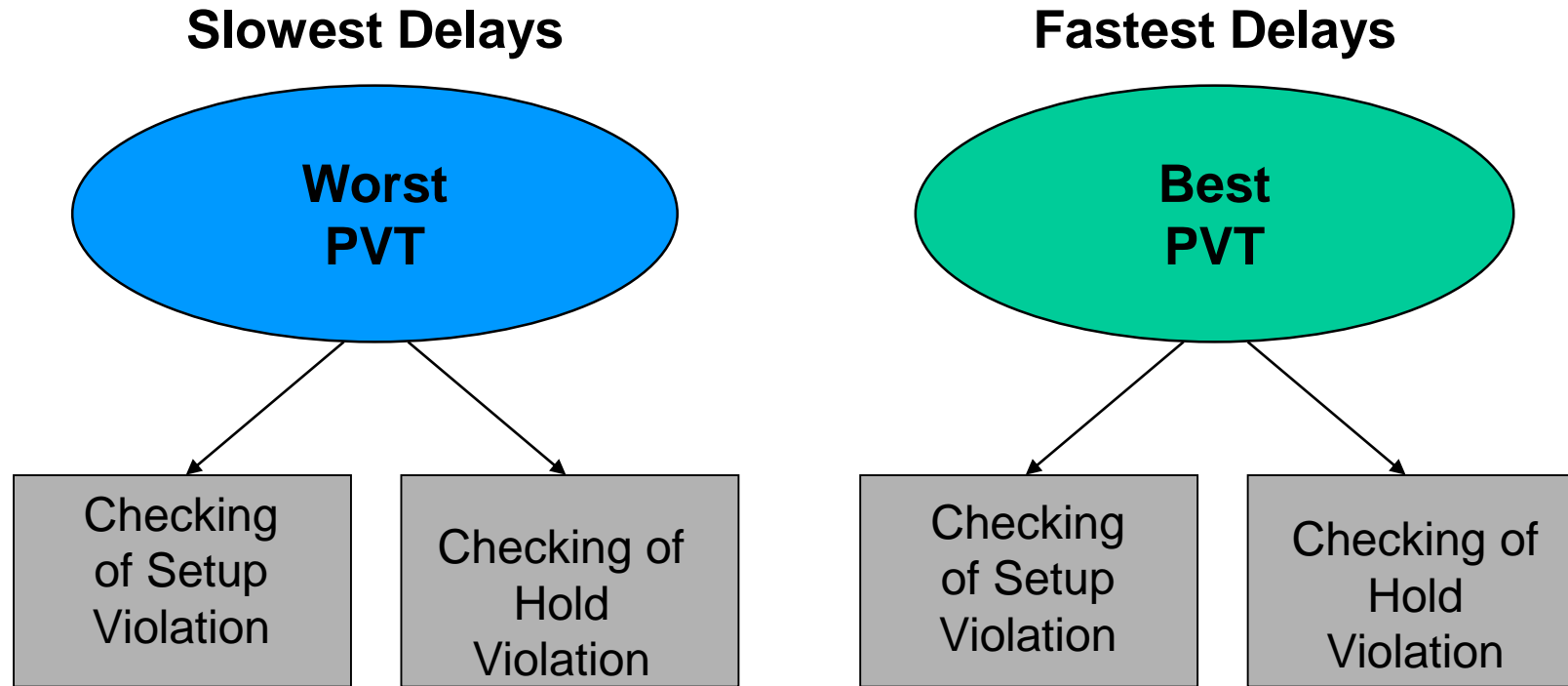
# Multi-Corner Problem



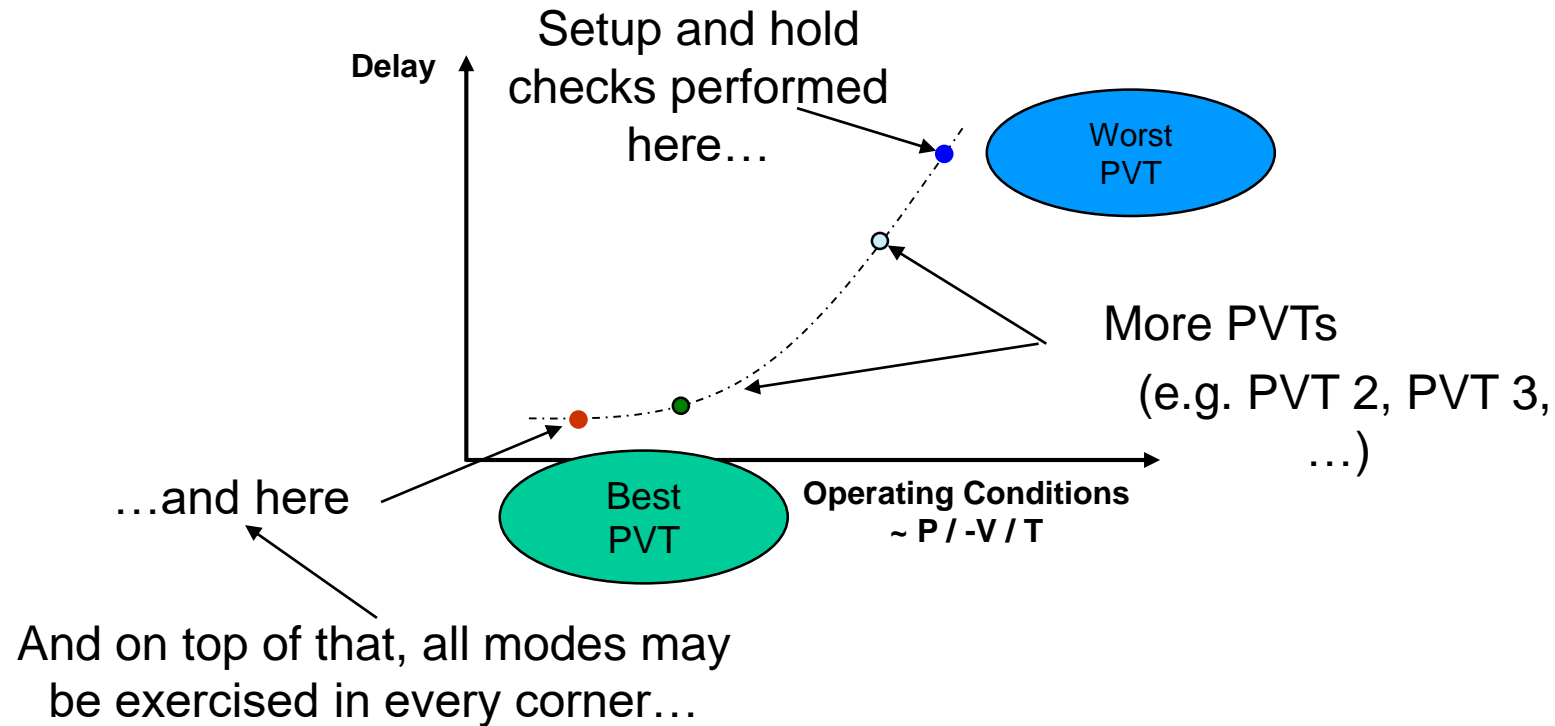
P: Process  
V: Voltage  
T: Temperature

A corner is defined as a PVT and it is provided to the tool as logic libraries per PVT and as parasitics data.

# Necessity of Multi Corner Analysis



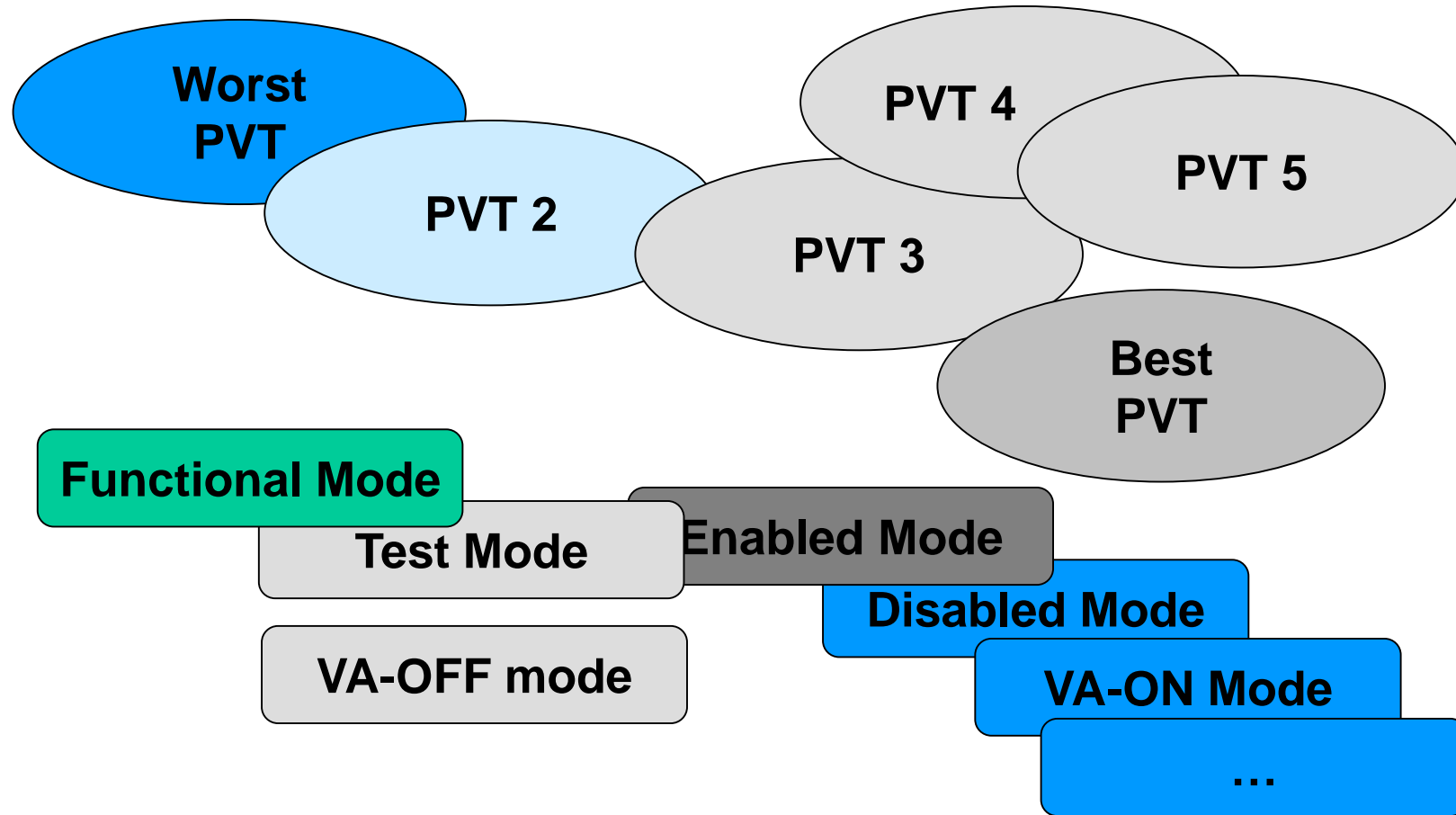
# Combination of Corners and Modes



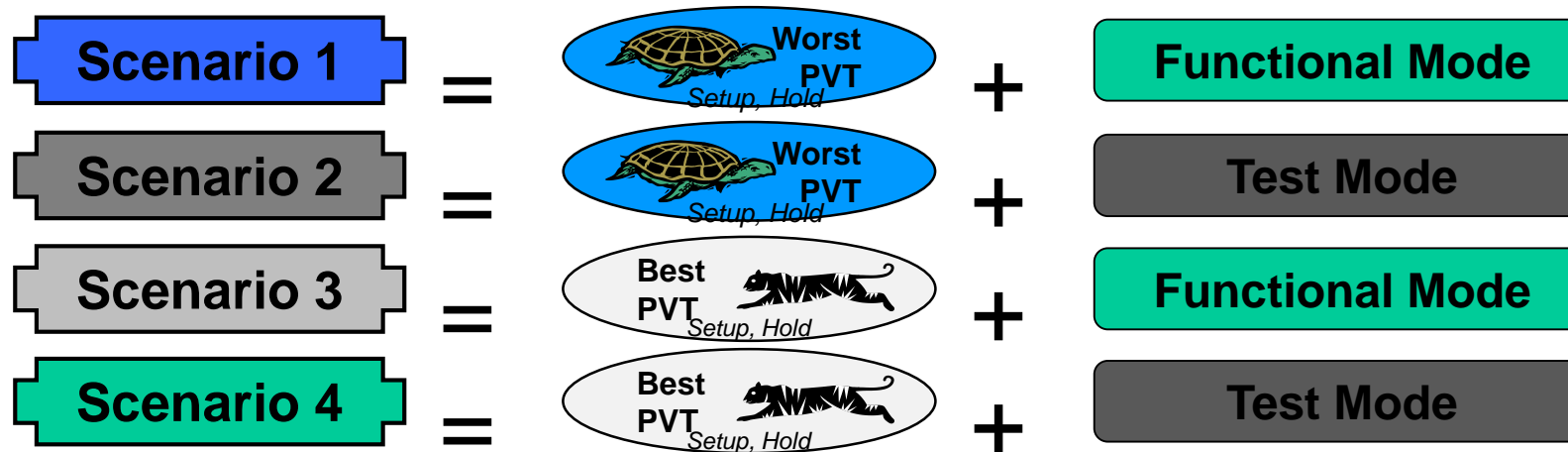
Number of runs = number of Modes x number of PVT corners



# Multiple Corners – Multiple Modes

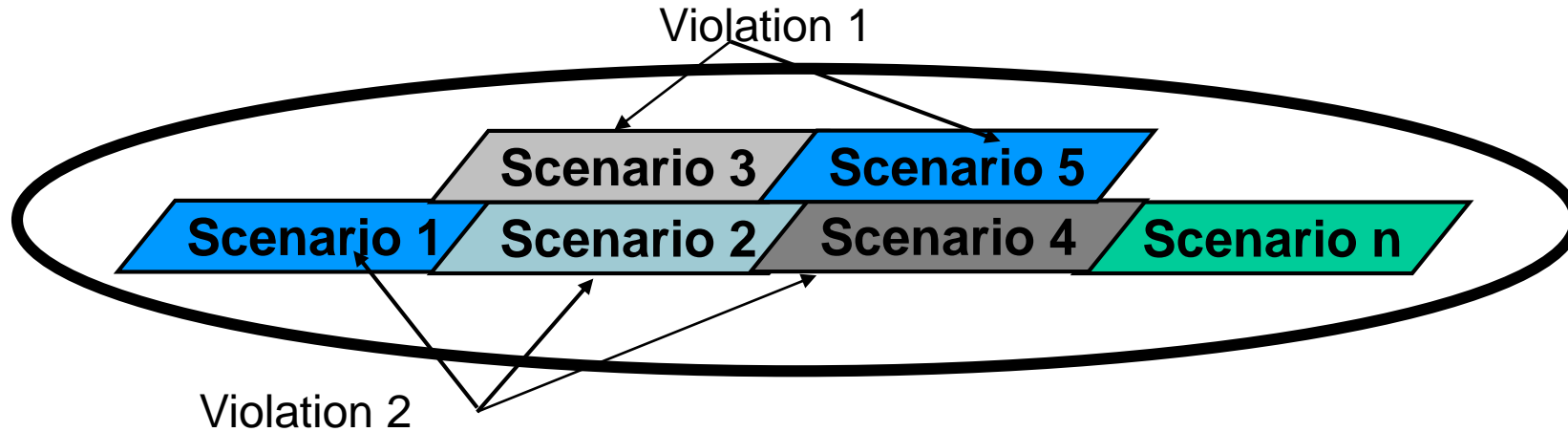


# Scenarios



# Fixing of Violations

Optimizing single scenario is challenging -> MM/MC is much challenging



Multi-Mode / Multi-Corner

- Concurrent MM/MC optimization works on all violations and on all scenarios thereby eliminating the convergence problems observed in sequential approaches.
- Optimization is performed for timing, power (leakage), noise, DRC, area, etc.
- **MM/MC optimization** utilizes a concurrent costing engine which ensures that every transformation is acceptable for all scenarios' costs.

# Chip Finishing

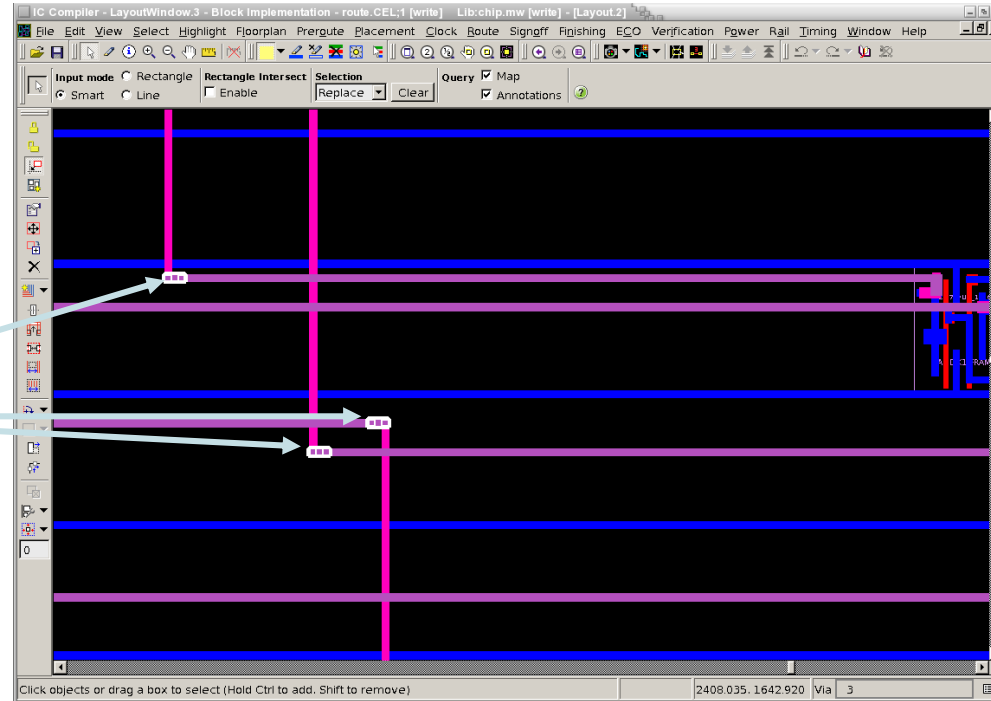
Still a few more steps to finish the implementation...

# Redundant Vias

- Redundant via insertion is a widely recommended technique to enhance the via yield and reliability

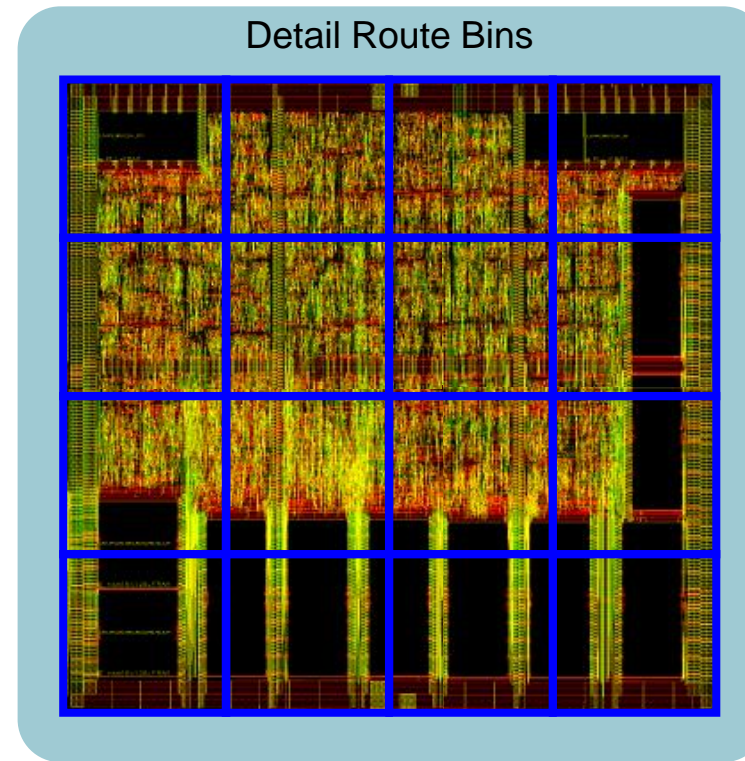
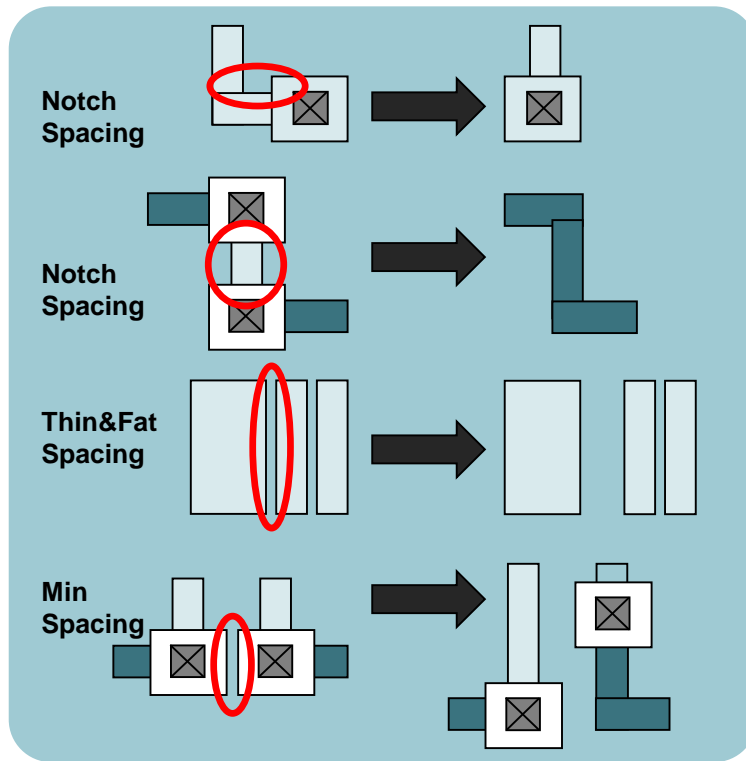
Redundant via doubles the number via  
If one of them will not be made chip will still work

Redundant Vias



# Search and Repair

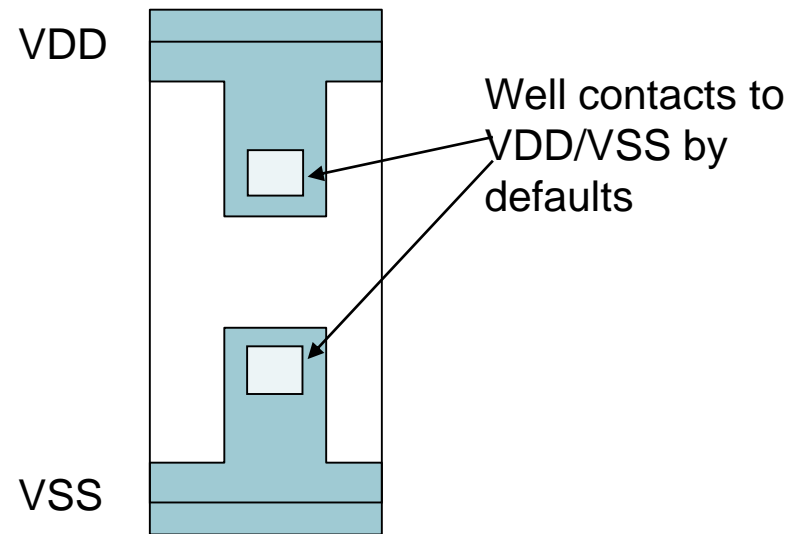
Detail route attempts to clear DRC violations using a fixed size bin



source: Synopsys

# Filler Cells

Filler cells are inserted to fill empty places among standard cells



# Writing out the netlist

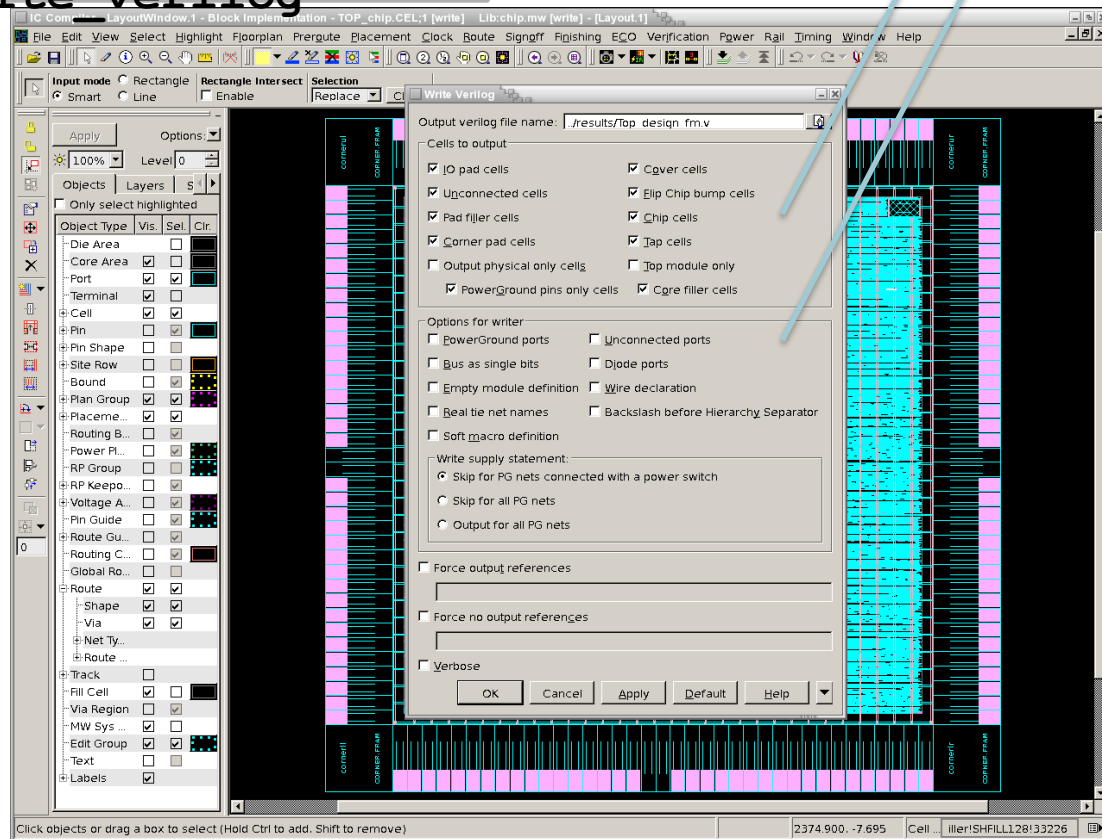
File → Write Verilog

icc\_shell>

write\_verilog

Cells to Output

Options for Write

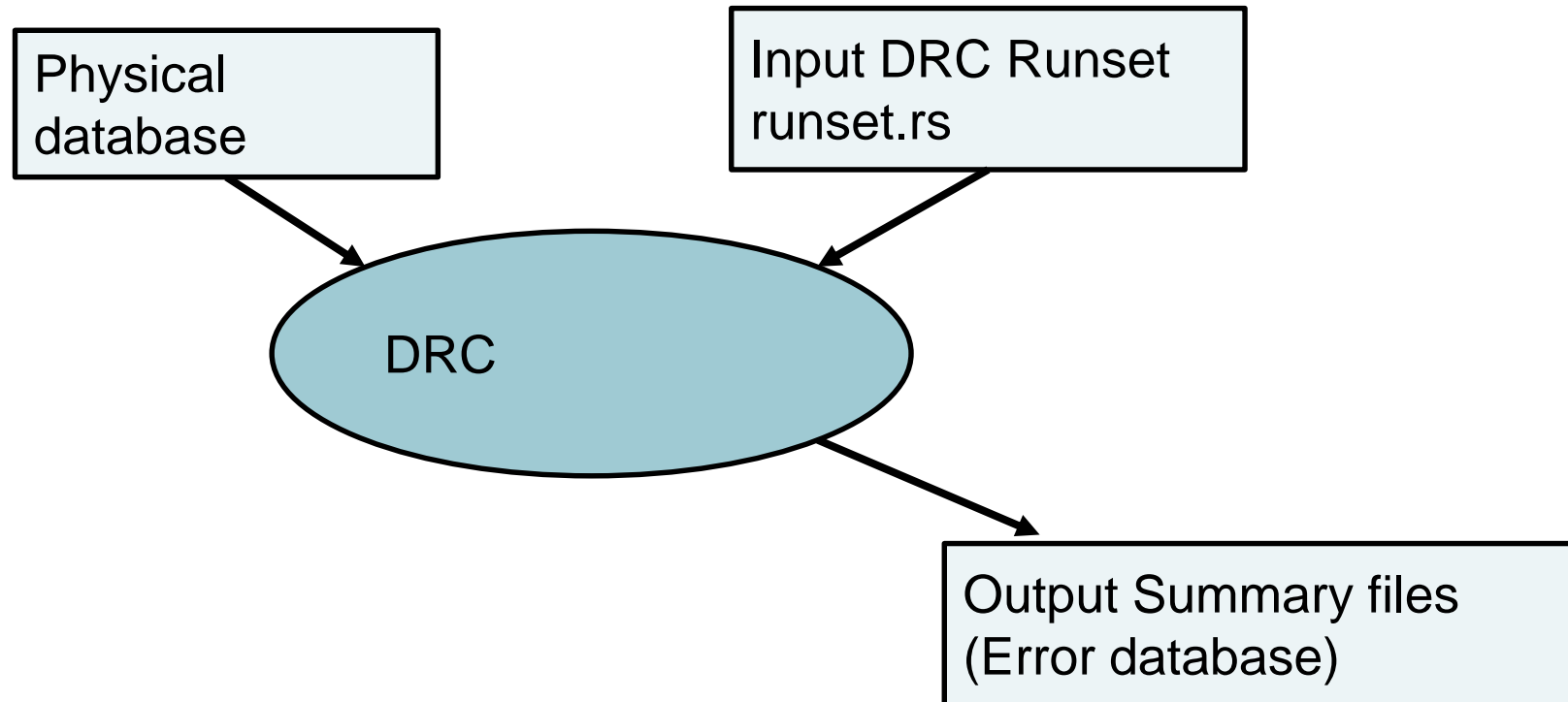




# Signoff

Ready to tape out? Wait...

# DRC Flow



# DRC Errors Windows

DRC violation types

Number of DRC violations

Information about selected violation

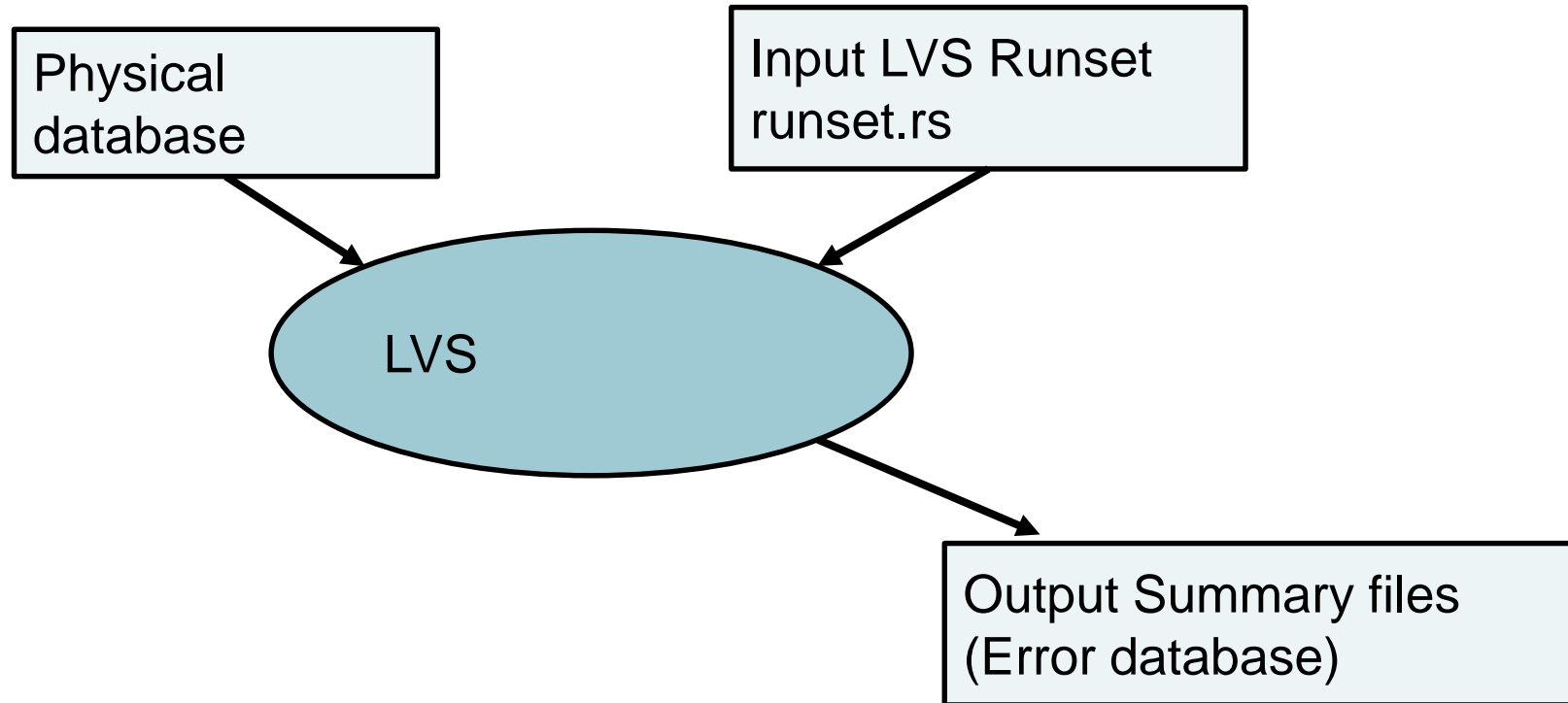
Error Set	Total	Visible	Fixed
route_lvs.err:1	110	110	0
Floating Net	1	1	0
Floating Port	20	20	0
Min Area	66	66	0
Open	3	3	0
Short	20	20	0

#	Id	Color	Type	Layer
0	1536		Min Area	
1	1537		Min Area	
2	1538		Min Area	
3	1539		Min Area	
4	1540		Min Area	
5	1541		Min Area	
6	1542		Min Area	
7	1543		Min Area	
8	1544		Min Area	
9	1545		Min Area	
10	1546		Min Area	

0: Layer: Type: Min Area  
Type Summary : Minimum Area Errors have been detected by LVS.  
Obj Info : area [(350.400,354.360), (350.560,354.600)] 0.0384 um sqr.  
Error ID: 1536 Status: Not Fixed  
Bbox : (350.400 354.360) (350.560 354.600)

# Layout Versus Schematic (LVS)



# LVS Errors Windows

LVS violation types

Number of LVS violations

Information about selected violation

The screenshot shows the IC Compiler interface with the LVS Error Browser window open. The window displays a table of violations and a detailed view of a selected violation.

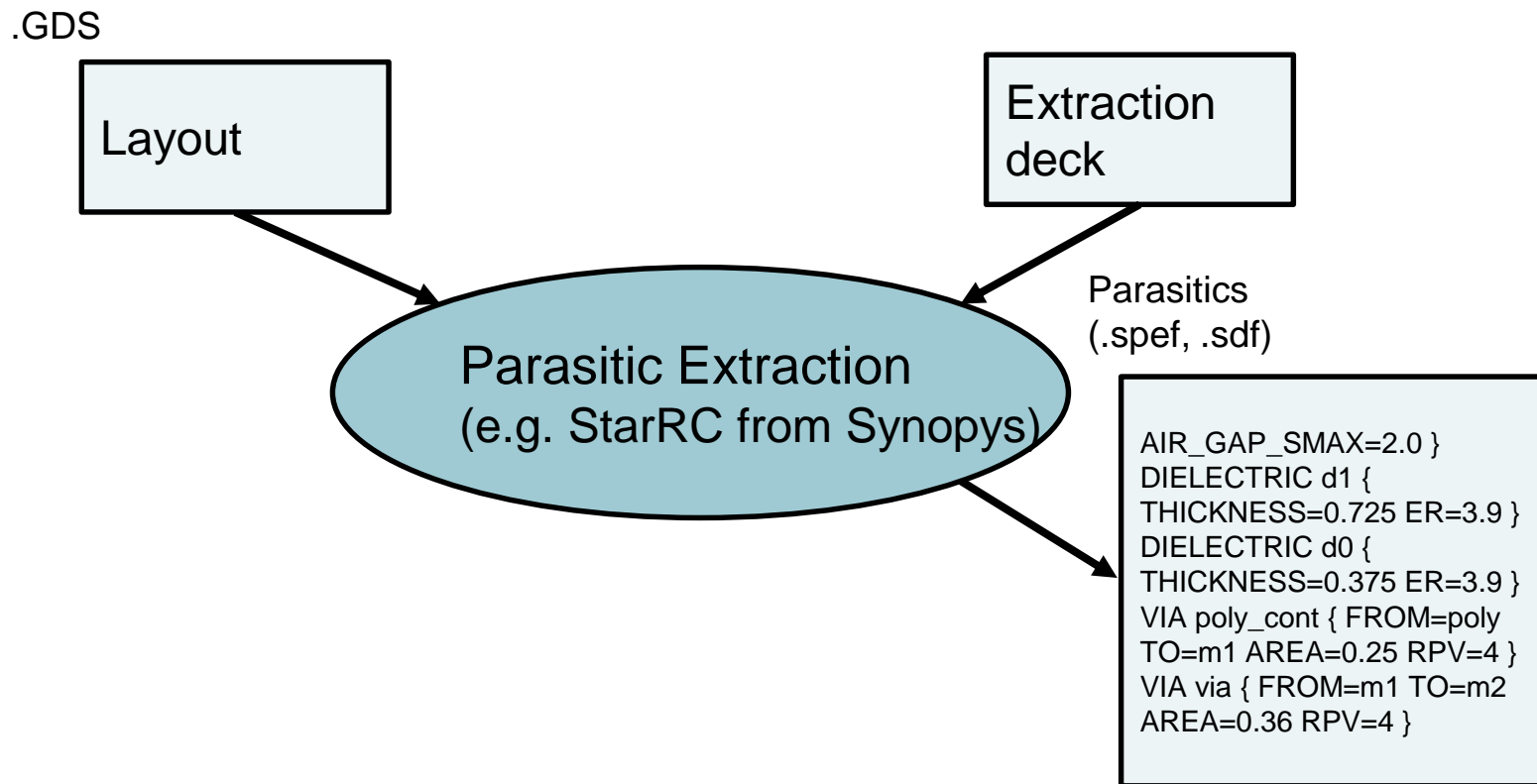
Error Set	Total	Visible	Fixed
route_lvs.err:1	110	110	0
Floating Net	1	1	0
Floating Port	20	20	0
Min Area	66	66	0
Open	3	3	0
Short	20	20	0

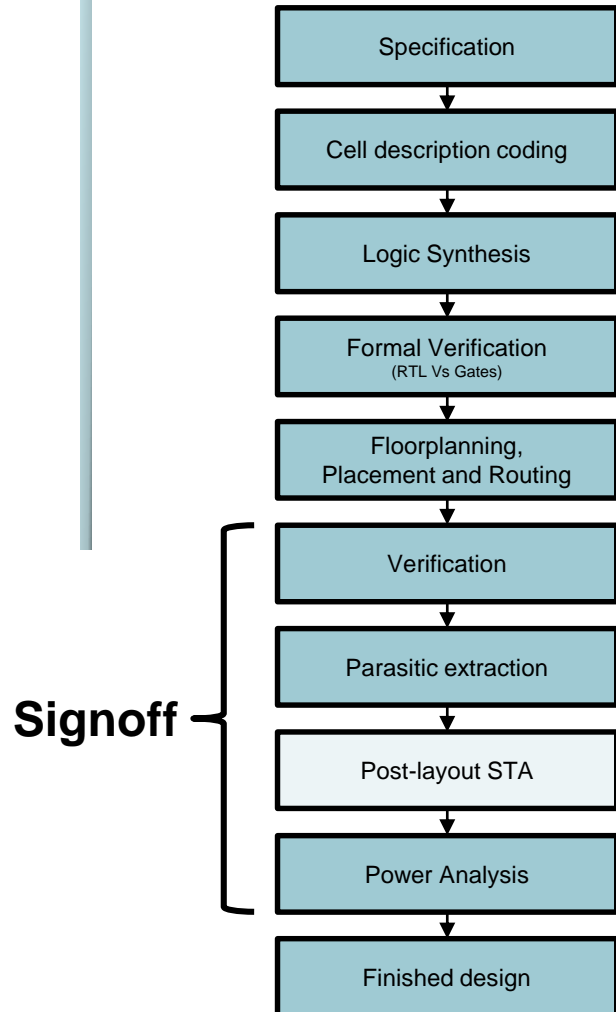
#	Id	Color	Type	Layer
0	14606		Open	
1	14607		Open	
2	14608		Open	

0: Layer: Type: Open  
Net type: Signal  
Type Summary : OPENS have been detected by LVS.  
Obj Info : Logical Net U2/u\_logic/m4995 is open.  
Net: U2/u\_logic/m4995

# Parasitic Extraction



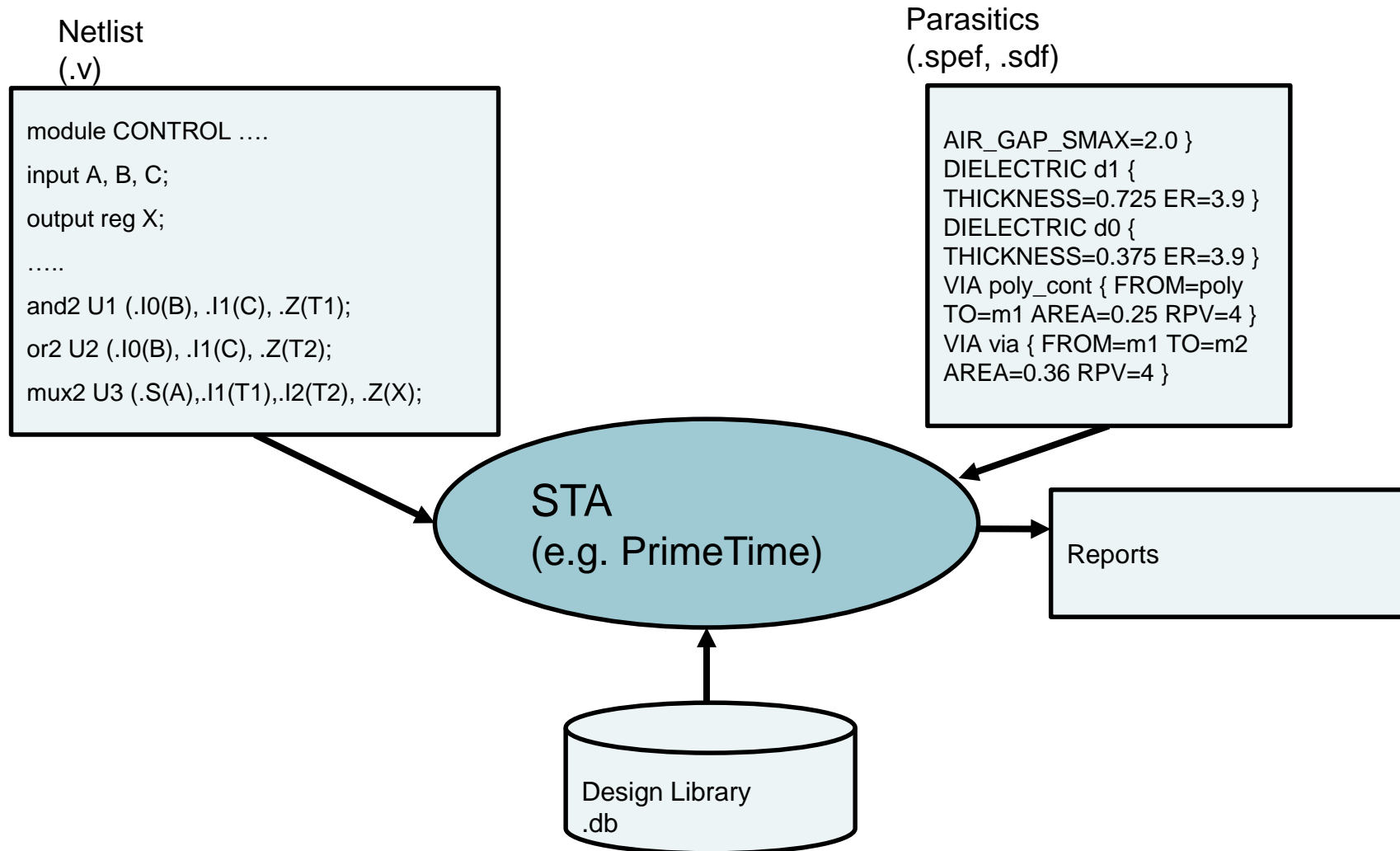
# Back to the flow



## PrimeTime (Synopsys tool) and STA

- PrimeTime is a full-chip, gate-level static timing analysis tool that is an essential part of the design and analysis flow for today's large chip designs
- PrimeTime validates the timing performance of a design by checking all possible paths for timing violations, without using logic simulation or test vectors

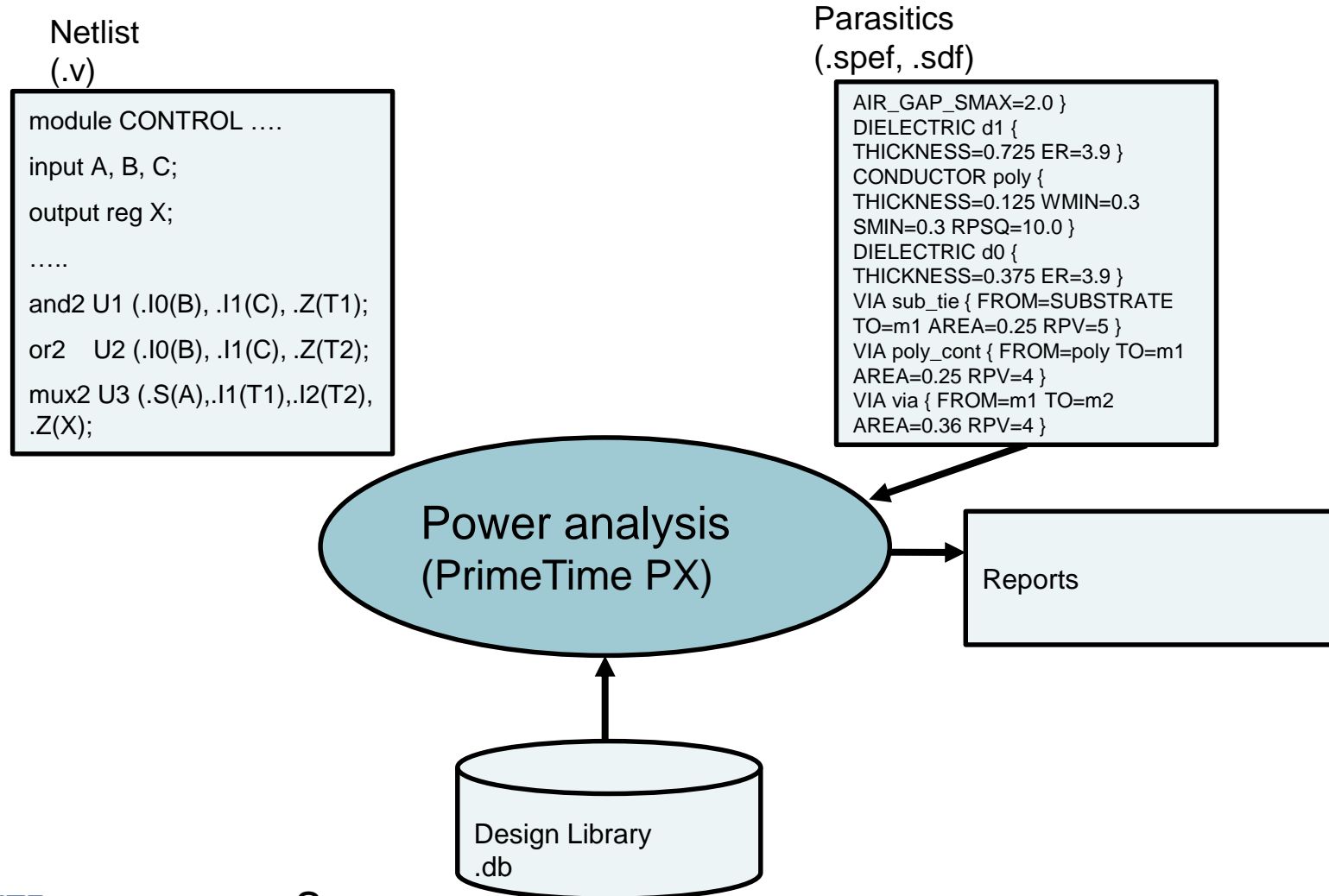
# STA Flow



source: Synopsys

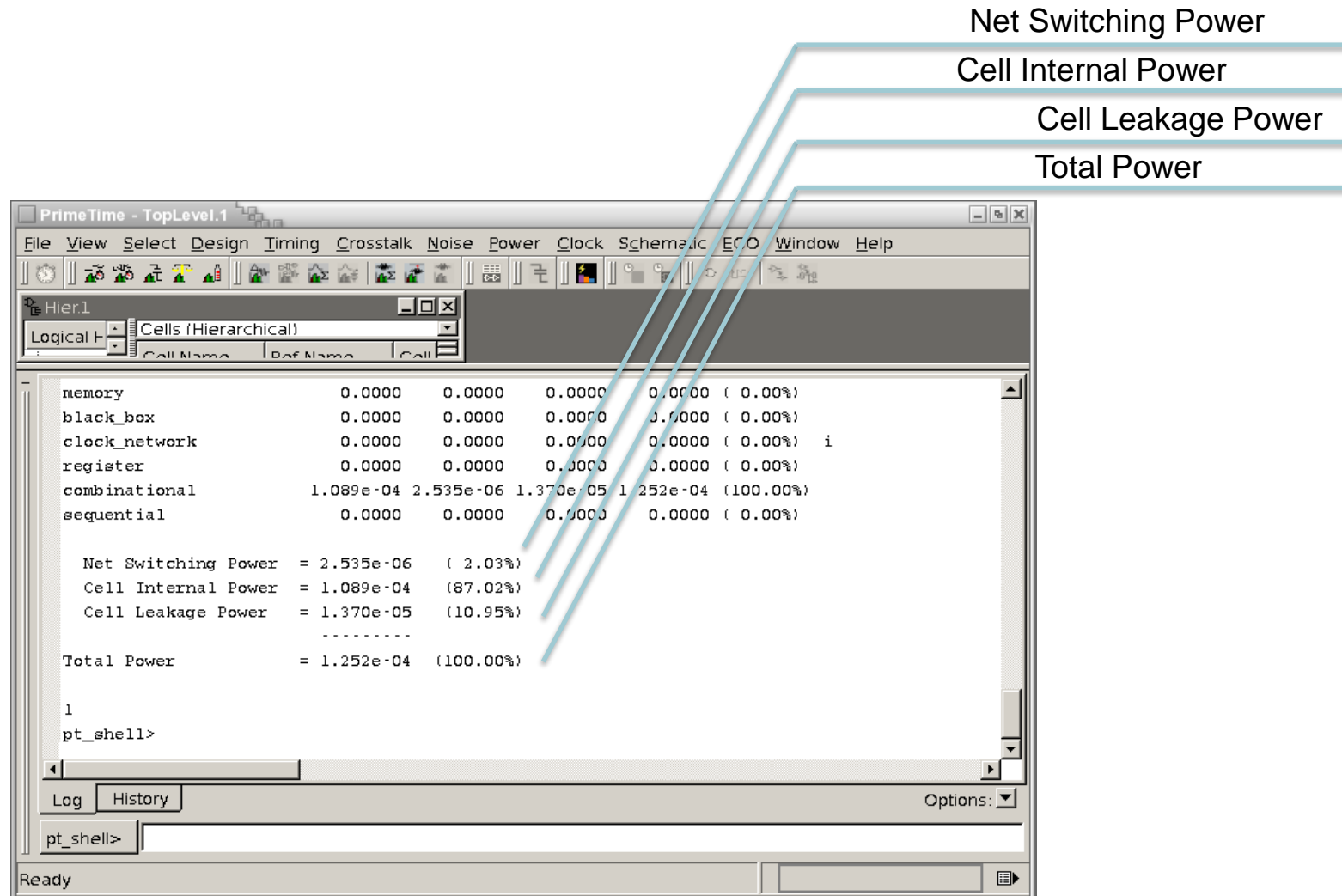


# Power analysis



source: Synopsys

# Report power



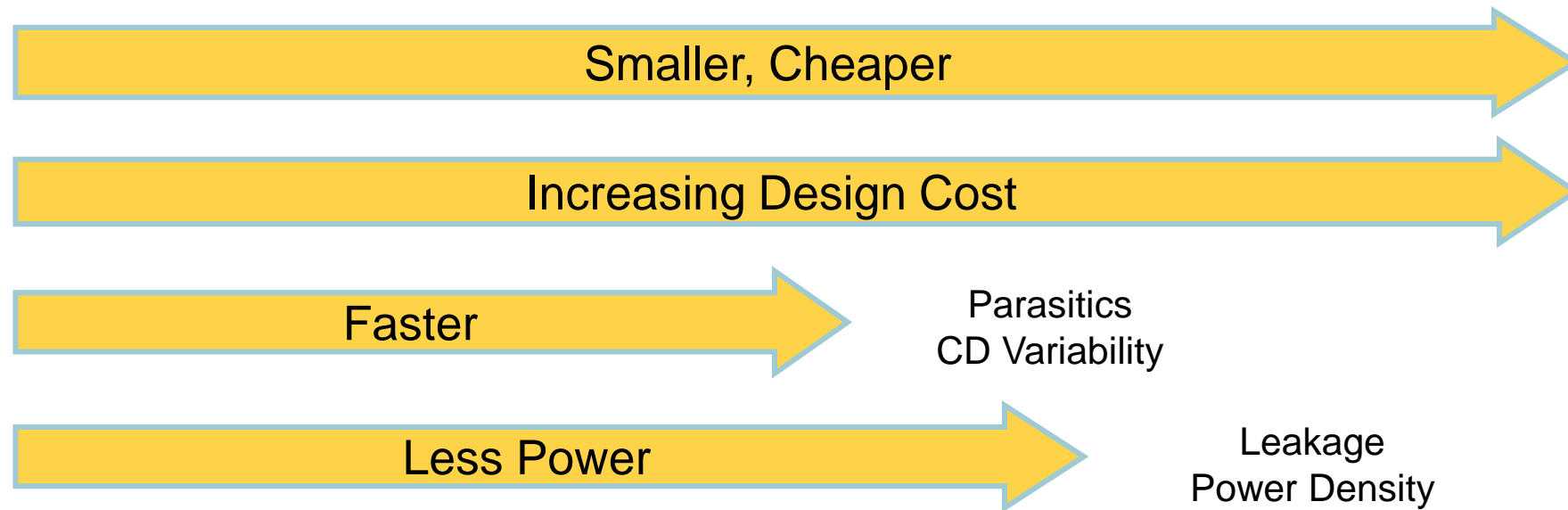
source: Synopsys

# Summary

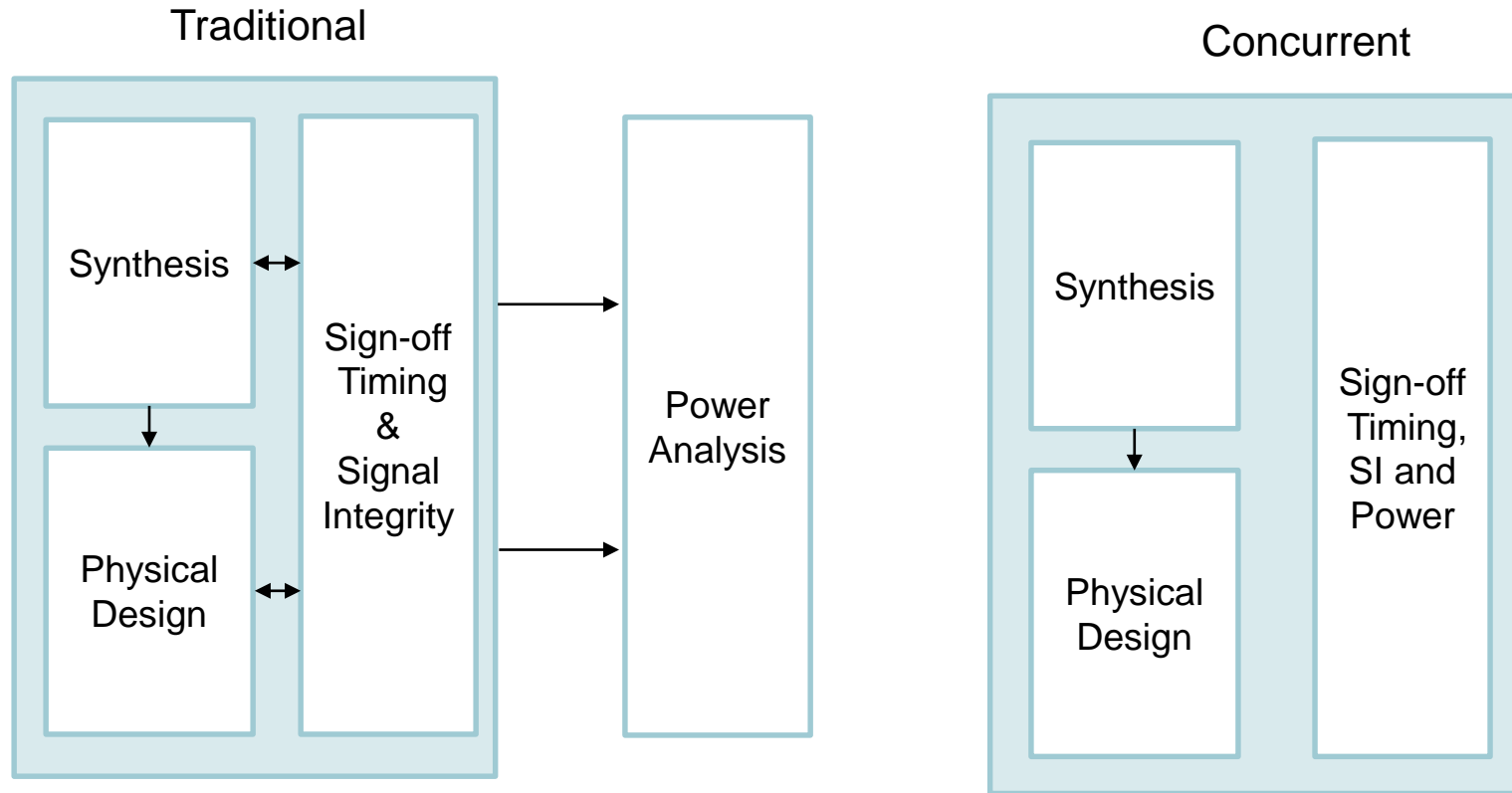
- A full view of how chip design process is done, and what are the considerations of each step
- Chip design flow is VERY complex, everything needs to be scripted up...
- EDA tools are not as intelligent as what you would think
- A lot of design efforts, Human-EDA interfacing
- What are not covered in this lecture
  - Design for test
  - Chip testing
  - Verification
  - Many more...

# Challenges start from technology scaling

1μm	.7μm	.5μm	.35μm	.25μm	.18μm	.13μm	90nm	65nm	45nm	32nm		
1986	1992	1995	1997	1999	2000	2002	2003	2004	2006	2008	2010	2011



# Concurrent Design Methodology



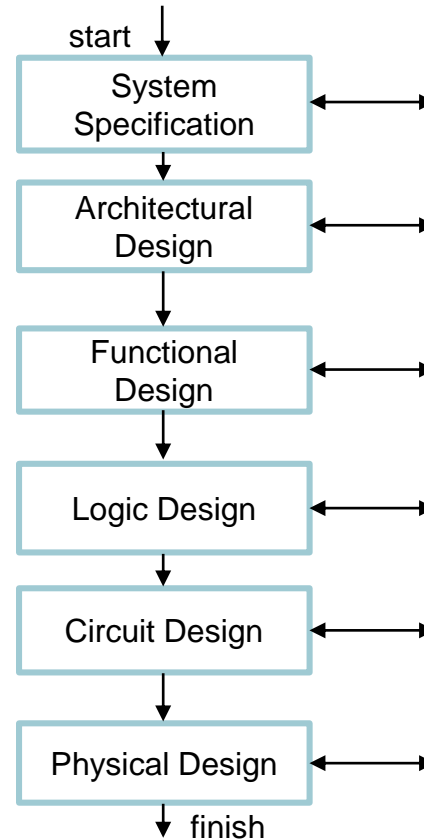
source: Synopsys

# New Challenges in the Design Flow

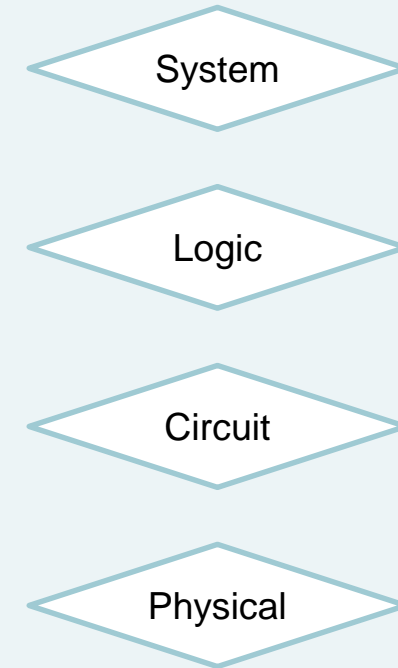
## ■ Design Challenges

- IP
- Timing closure
- Signal integrity
- Leakage power
- Dynamic power
- Test
- Yield
- Printability

### Design Implementation



### Design Verification

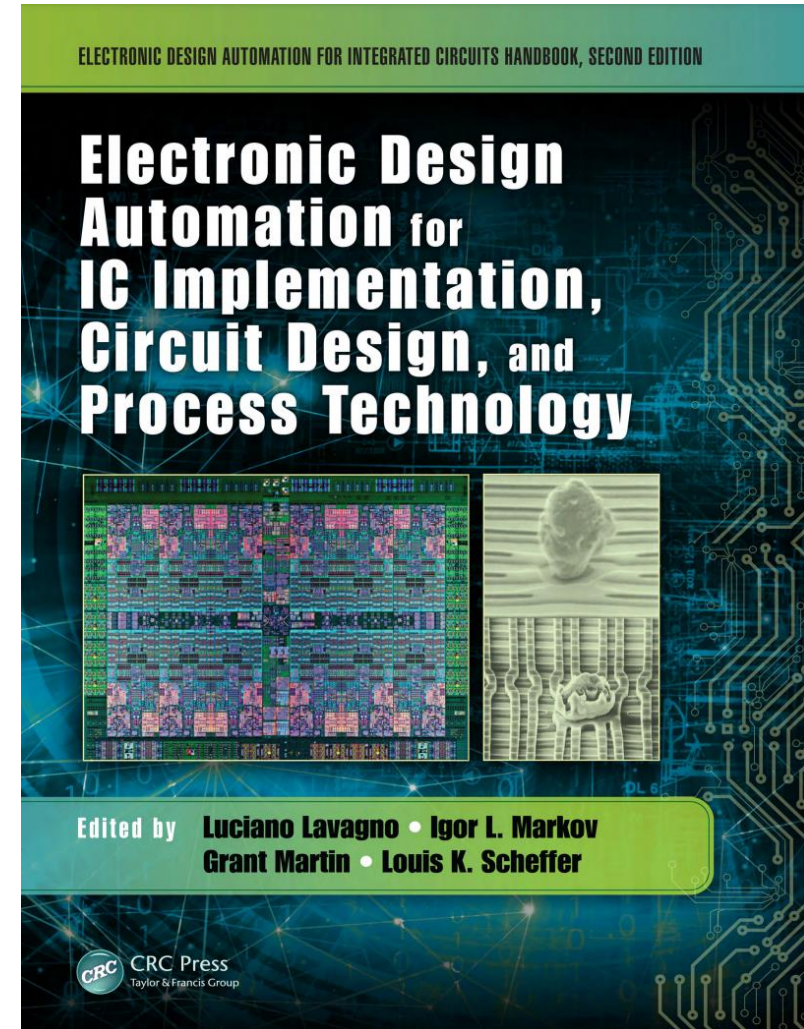


# Where are we Heading?

- SoC Design Space

# Action Items

- Reading Materials
  - Slides
  - Ch. 1 & 2 of Electronic Design Automation for IC Implementation, Circuit Design, and Process Technology (on canvas)





# Acknowledgement

Slides in this topic are inspired in part by material developed and copyright by:

- Synopsys Courseware
- Prof. Christopher Batten @ Cornell University